

PRODUCT SPECIFICATIONS

SHARP®

Integrated Circuits Group

LRS1805A

Stacked Chip

64M (x16) Flash Memory + 16M (x16) Smartcombo RAM

(Model No.: LRS1805A)

Spec No.: EL139030

Issue Date: September 18, 2001



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1. Description

The LRS1805A is a combination memory organized as 4,194,304 x16 bit flash memory and 1,048,576 x16 bit Smartcombo RAM in one package.

Features

- Power supply
 - • • • 2.7V to 3.3V(Flash)
 - • • • 2.7V to 3.1V(Smartcombo RAM)
- Operating temperature
 - • • • -25°C to +85°C
- Not designed or rated as radiation hardened
- 72pin CSP (LCSP072-P-0811) plastic package
- Flash memory has P-type bulk silicon, and Smartcombo RAM has P-type bulk silicon

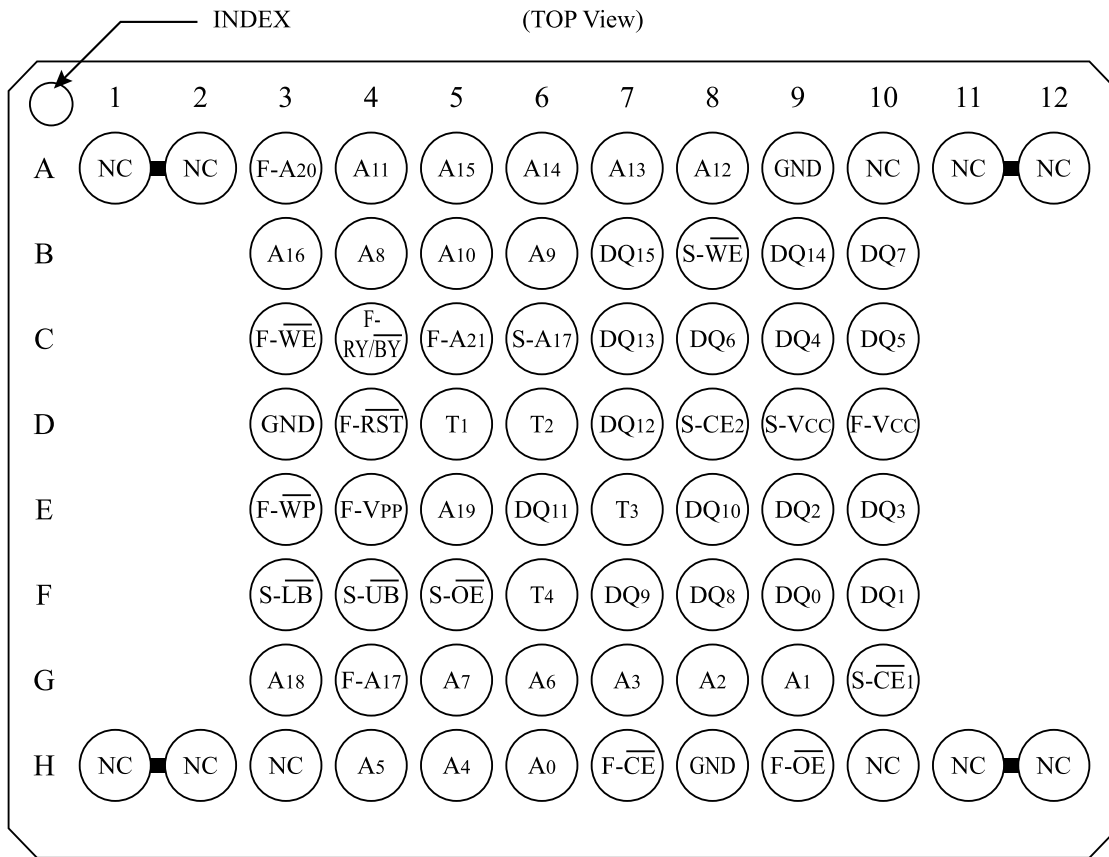
Flash Memory

- Access Time
 - • • • 85 ns (Max.)
- Power supply current (The current for F-V_{CC} pin and F-V_{PP} pin)
 - Read
 - • • • 25 mA (Max. t_{CYCLE} = 200ns, CMOS Input)
 - Word write
 - • • • 60 mA (Max.)
 - Block erase
 - • • • 30 mA (Max.)
 - Reset Power-Down
 - • • • 25 μA (Max. F- $\overline{\text{RST}}$ = GND ± 0.2V,
I_{OUT} (F-RY/ $\overline{\text{BY}}$) = 0mA)
 - Standby
 - • • • 25 μA (Max. F- $\overline{\text{CE}}$ = F- $\overline{\text{RST}}$ = F-V_{CC} ± 0.2V)
- Optimized Array Blocking Architecture
 - Eight 4K-word Parameter Blocks
 - One-hundred and twenty-seven 32K-word Main Blocks
 - Top Parameter Location
- Extended Cycling Capability
 - 100,000 Block Erase Cycles (F-V_{PP} = 1.65V to 3.3V)
 - 1,000 Block Erase Cycles and total 80 hours (F-V_{PP} = 11.7V to 12.3V)
- Enhanced Automated Suspend Options
 - Word Write Suspend to Read
 - Block Erase Suspend to Word Write
 - Block Erase Suspend to Read

Smartcombo RAM

- Access Time
 - • • • 85 ns (Max.)
- Cycle time
 - • • • 85 to 32,000 ns
- Power Supply current
 - Operating current
 - • • • 20 mA (Max. t_{RC}, t_{WC} = Min.)
 - Standby current (Data retention current)
 - • • • 80 μA (Max.)
 - Sleep Mode (Data non-retention current)
 - • • • 15 μA (Max.)

2. Pin Configuration



Note) From T1 to T4 pins are needed to be open.
 Two NC pins at the corner are connected.
 Do not float any GND pins.

Pin	Description	Type
A ₀ to A ₁₆ , A ₁₈ , A ₁₉	Address Inputs (Common)	Input
F-A ₁₇ , F-A ₂₀ , F-A ₂₁	Address Inputs (Flash)	Input
S-A ₁₇	Address Input (Smartcombo RAM)	Input
F- $\overline{\text{CE}}$	Chip Enable Input (Flash)	Input
S- $\overline{\text{CE}}_1$	Chip Enable Input (Smartcombo RAM)	Input
S-CE ₂	Sleep State Input (Smartcombo RAM)	Input
F- $\overline{\text{WE}}$	Write Enable Input (Flash)	Input
S- $\overline{\text{WE}}$	Write Enable Input (Smartcombo RAM)	Input
F- $\overline{\text{OE}}$	Output Enable Input (Flash)	Input
S- $\overline{\text{OE}}$	Output Enable Input (Smartcombo RAM)	Input
S- $\overline{\text{LB}}$	Smartcombo RAM Byte Enable Input (DQ ₀ to DQ ₇)	Input
S- $\overline{\text{UB}}$	Smartcombo RAM Byte Enable Input (DQ ₈ to DQ ₁₅)	Input
F- $\overline{\text{RST}}$	Reset Power Down Input (Flash) Block erase and Write : V _{IH} Read : V _{IH} Reset Power Down : V _{IL}	Input
F- $\overline{\text{WP}}$	Write Protect Input (Flash) When F- $\overline{\text{WP}}$ is V _{IL} , locked-down blocks cannot be unlocked. Erase or program operation can be executed to the blocks which are not locked and locked-down. When F- $\overline{\text{WP}}$ is V _{IH} , lock-down is disabled.	Input
F-RY/ $\overline{\text{BY}}$	Ready/Busy Output (Flash) During an Erase or Write operation : V _{OL} Block Erase and Write Suspend : High-Z (High impedance)	Open Drain Output
DQ ₀ to DQ ₁₅	Data Inputs and Outputs (Common)	Input / Output
F-V _{CC}	Power Supply (Flash)	Power
S-V _{CC}	Power Supply (Smartcombo RAM)	Power
F-V _{PP}	Monitoring Power Supply Voltage (Flash) Block Erase and Write : F-V _{PP} = V _{PPH1/2} All Blocks Locked : F-V _{PP} < V _{PPLK}	Input
GND	GND (Common)	Power
NC	Non Connection	-
T ₁ to T ₄	Test pins (Should be all open)	-

3. Truth Table

3.1 Bus Operation⁽¹⁾

Flash	Smart combo RAM	Notes	F- \overline{CE}	F- \overline{RST}	F- \overline{OE}	F- \overline{WE}	S- \overline{CE}_1	S- \overline{CE}_2	S- \overline{OE}	S- \overline{WE}	S- \overline{LB}	S- \overline{UB}	DQ ₀ to DQ ₁₅		
Read	Standby	3,5	L	H	L	H	H	H	X	X	X	X	(7)		
Output Disable		5			H								High - Z		
Write		2,3,4,5			L								D _{IN}		
Read	Sleep	3,5	L	H	L	H	X	L	X	X	X	X	(7)		
Output Disable		5			H								High - Z		
Write		2,3,4,5			L								D _{IN}		
Standby	Read	5,6	H	H	X	X	L	H	L	H	(8)		High - Z		
	Output Disable	5,6							X	X	H	H		X	X
	Write	5,6							X	L	(8)				
Reset Power Down	Read	5,6	X	L	X	X	L	H	L	H	(8)		High - Z		
	Output Disable	5,6							X	X	H	H		X	X
	Write	5,6							X	L	(8)				
Standby	Standby	5	H	H	X	X	H	H	X	X	X	X	High - Z		
Reset Power Down		5,6	X	L											
Standby	Sleep	5	H	H	X	X	X	L	X	X	X	X	High - Z		
Reset Power Down		5,6	X	L											

Notes:

- L = V_{IL}, H = V_{IH}, X = H or L, High-Z = High impedance. Refer to the DC Characteristics.
- Command writes involving block erase (page buffer) program are reliably executed when F-V_{PP} = V_{PPH1/2} and F-V_{CC} = 2.7V to 3.3V.
Command writes involving full chip erase is reliably executed when F-V_{PP} = V_{PPH1} and F-V_{CC} = 2.7V to 3.3V.
Block erase, full chip erase, (page buffer) program with F-V_{PP} < V_{PPH1/2} (Min.) produce spurious results and should not be attempted.
- Never hold F- \overline{OE} low and F- \overline{WE} low at the same timing.
- Refer Section 5. Command Definitions for Flash Memory valid D_{IN} during a write operation.
- F- \overline{WP} set to V_{IL} or V_{IH}.
- Electricity consumption of Flash Memory is lowest when F- \overline{RST} = GND ±0.2V.

7. Flash Read Mode

Mode	Address	DQ ₀ to DQ ₁₅
Read Array	X	D _{OUT}
Read Identifier Codes	See 5.2	See 5.2
Read Query	Refer to the Appendix	Refer to the Appendix

8. S- \overline{UB} , S- \overline{LB} Control Mode

S- \overline{LB}	S- \overline{UB}	DQ ₀ to DQ ₇	DQ ₈ to DQ ₁₅
L	L	D _{OUT} /D _{IN}	D _{OUT} /D _{IN}
L	H	D _{OUT} /D _{IN}	High - Z
H	L	High - Z	D _{OUT} /D _{IN}

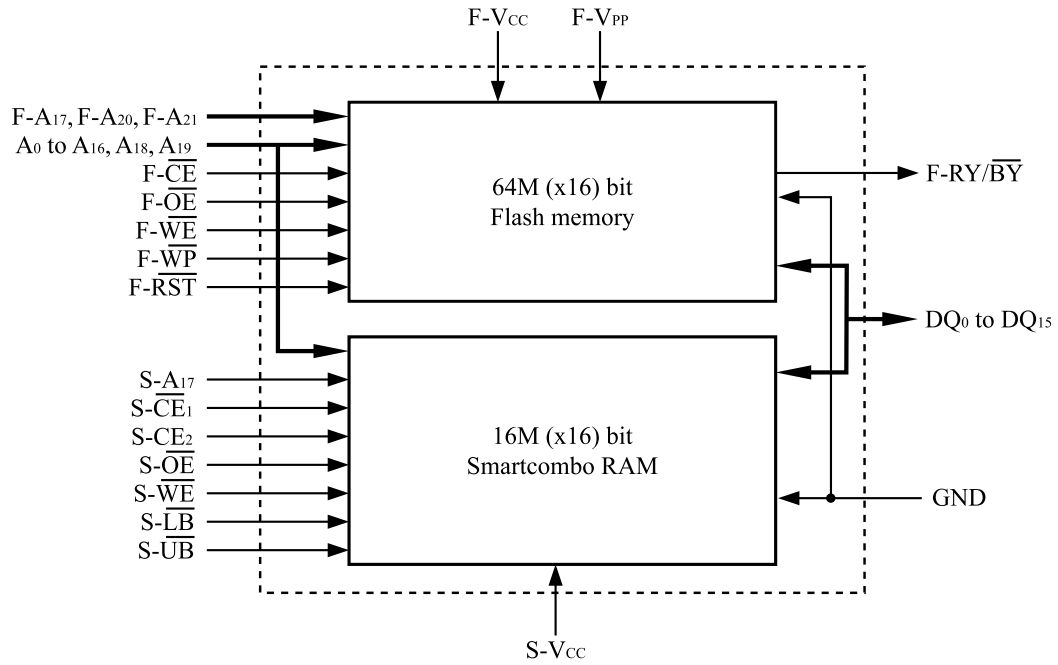
3.2 Simultaneous Operation Modes Allowed with Four Planes^(1, 2)

IF ONE PARTITION IS:	THEN THE MODES ALLOWED IN THE OTHER PARTITION IS:									
	Read Array	Read ID	Read Status	Read Query	Word Program	Page Buffer Program	Block Erase	Full Chip Erase	Program Suspend	Block Erase Suspend
Read Array	X	X	X	X	X	X	X		X	X
Read ID	X	X	X	X	X	X	X		X	X
Read Status	X	X	X	X	X	X	X	X	X	X
Read Query	X	X	X	X	X	X	X		X	X
Word Program	X	X	X	X						X
Page Buffer Program	X	X	X	X						X
Block Erase	X	X	X	X						
Full Chip Erase			X							
Program Suspend	X	X	X	X						X
Block Erase Suspend	X	X	X	X	X	X			X	

Notes:

1. "X" denotes the operation available.
2. Configurative Partition Dual Work Restrictions:
 Status register reflects partition state, not WSM (Write State Machine) state - this allows a status register for each partition.
 Only one partition can be erased or programmed at a time - no command queuing.
 Commands must be written to an address within the block targeted by that command.

4. Block Diagram



5. Command Definitions for Flash Memory⁽¹¹⁾

5.1 Command Definitions

Command	Bus Cycles Req'd	Notes	First Bus Cycle			Second Bus Cycle		
			Oper ⁽¹⁾	Address ⁽²⁾	Data ⁽³⁾	Oper ⁽¹⁾	Address ⁽²⁾	Data ⁽³⁾
Read Array	1	2	Write	PA	FFH			
Read Identifier Codes	≥ 2	2,3,4	Write	PA	90H	Read	IA	ID
Read Query	≥ 2	2,3,4	Write	PA	98H	Read	QA	QD
Read Status Register	2	2,3	Write	PA	70H	Read	PA	SRD
Clear Status Register	1	2	Write	PA	50H			
Block Erase	2	2,3,5	Write	BA	20H	Write	BA	D0H
Full Chip Erase	2	2,5,9	Write	X	30H	Write	X	D0H
Program	2	2,3,5,6	Write	WA	40H or 10H	Write	WA	WD
Page Buffer Program	≥ 4	2,3,5,7	Write	WA	E8H	Write	WA	N-1
Block Erase and (Page Buffer) Program Suspend	1	2,8,9	Write	PA	B0H			
Block Erase and (Page Buffer) Program Resume	1	2,8,9	Write	PA	D0H			
Set Block Lock Bit	2	2	Write	BA	60H	Write	BA	01H
Clear Block Lock Bit	2	2,10	Write	BA	60H	Write	BA	D0H
Set Block Lock-down Bit	2	2	Write	BA	60H	Write	BA	2FH
Set Partition Configuration Register	2	2,3	Write	PCRC	60H	Write	PCRC	04H

Notes:

- Bus operations are defined in 3.1 Bus Operation.
- The address which is written at the first bus cycle should be the same as the address which is written at the second bus cycle.
 X=Any valid address within the device.
 PA=Address within the selected partition.
 IA=Identifier codes address (See 5.2 Identifier Codes for Read Operation).
 QA=Query codes address. Refer to the LH28F320BF, LH28F640BF series Appendix for details.
 BA=Address within the block being erased, set/cleared block lock bit or set block lock-down bit.
 WA=Address of memory location for the Program command or the first address for the Page Buffer Program command.
 PCRC=Partition configuration register code presented on the address A₀-A₁₅.
- ID=Data read from identifier codes (See 5.2 Identifier Codes for Read Operation).
 QD=Data read from query database. Refer to the LH28F320BF, LH28F640BF series Appendix for details.
 SRD=Data read from status register. See 6. Status Register Definition for a description of the status register bits.
 WD=Data to be programmed at location WA. Data is latched on the rising edge of F- \overline{WE} or F- \overline{CE} (whichever goes high first).
 N-1=N is the number of the words to be loaded into a page buffer.
- Following the Read Identifier Codes command, read operations access manufacturer code, device code, block lock configuration code, partition configuration register code (See 5.2 Identifier Codes for Read Operation).
 The Read Query command is available for reading CFI (Common Flash Interface) information.
- Block erase, full chip erase or (page buffer) program cannot be executed when the selected block is locked. Unlocked block can be erased or programmed when F-RST is V_{IH}.
- Either 40H or 10H are recognized by the CUI (Command User Interface) as the program setup.
- Following the third bus cycle, inputs the program sequential address and write data of "N" times. Finally, input the any valid address within the target partition to be programmed and the confirm command (D0H). Refer to the LH28F320BF, LH28F640BF series Appendix for details.

8. If the program operation in one partition is suspended and the erase operation in other partition is also suspended, the suspended program operation should be resumed first, and then the suspended erase operation should be resumed next.
9. Full chip erase operation can not be suspended.
10. Following the Clear Block Lock Bit command, block which is not locked-down is unlocked when $F\text{-}\overline{WP}$ is V_{IL} .
When $F\text{-}\overline{WP}$ is V_{IH} , lock-down bit is disabled and the selected block is unlocked regardless of lock-down configuration.
11. Commands other than those shown above are reserved by SHARP for future device implementations and should not be used.

5.2 Identifier Codes for Read Operation

	Code	Address [A ₁₅ -A ₀] ⁽⁴⁾	Data [DQ ₁₅ -DQ ₀]	Notes
Manufacturer Code	Manufacturer Code	0000H	00B0H	
Device Code	64M Top Parameter Device Code	0001H	00B0H	1
Block Lock Configuration Code	Block is Unlocked	Block Address + 2	DQ ₀ = 0	2
	Block is Locked		DQ ₀ = 1	2
	Block is not Locked-Down		DQ ₁ = 0	2
	Block is Locked-Down		DQ ₁ = 1	2
Device Configuration Code	Partition Configuration Register	0006H	PCRC	3

Notes:

1. Top parameter device has its parameter blocks in the plane 3 (The highest address).
2. DQ₁₅-DQ₂ is reserved for future implementation.
3. PCRC=Partition Configuration Register Code.
4. The address A₂₁-A₁₆ are shown in below table for reading the manufacturer, device, lock configuration, device configuration code.
The address to read the identifier codes is dependent on the partition which is selected when writing the Read Identifier Codes command (90H).
See Chapter 6. Partition Configuration Register Definition (P.15) for the partition configuration register.

Identifier Codes for Read Operation on Partition Configuration (64M-bit device)

Partition Configuration Register			Address (64M-bit device) [A ₂₁ -A ₁₆]
PCR.10	PCR.9	PCR.8	
0	0	0	00H
0	0	1	00H or 10H
0	1	0	00H or 20H
1	0	0	00H or 30H
0	1	1	00H or 10H or 20H
1	1	0	00H or 20H or 30H
1	0	1	00H or 10H or 30H
1	1	1	00H or 10H or 20H or 30H

5.3 Functions of Block Lock and Block Lock-Down

Current State					Erase/Program Allowed ⁽²⁾
State	F- \overline{WP}	DQ ₁ ⁽¹⁾	DQ ₀ ⁽¹⁾	State Name	
[000]	0	0	0	Unlocked	Yes
[001] ⁽³⁾	0	0	1	Locked	No
[011]	0	1	1	Locked-down	No
[100]	1	0	0	Unlocked	Yes
[101] ⁽³⁾	1	0	1	Locked	No
[110] ⁽⁴⁾	1	1	0	Lock-down Disable	Yes
[111]	1	1	1	Lock-down Disable	No

Notes:

1. DQ₀ = 1: a block is locked; DQ₀ = 0: a block is unlocked.
DQ₁ = 1: a block is locked-down; DQ₁ = 0: a block is not locked-down.
2. Erase and program are general terms, respectively, to express: block erase, full chip erase and (page buffer) program operations.
3. At power-up or device reset, all blocks default to locked state and are not locked-down, that is, [001] (F- \overline{WP} = 0) or [101] (F- \overline{WP} = 1), regardless of the states before power-off or reset operation.
4. When F- \overline{WP} is driven to V_{IL} in [110] state, the state changes to [011] and the blocks are automatically locked.

5.4 Block Locking State Transitions upon Command Write⁽⁴⁾

Current State				Result after Lock Command Written (Next State)		
State	F- \overline{WP}	DQ ₁	DQ ₀	Set Lock ⁽¹⁾	Clear Lock ⁽¹⁾	Set Lock-down ⁽¹⁾
[000]	0	0	0	[001]	No Change	[011] ⁽²⁾
[001]	0	0	1	No Change ⁽³⁾	[000]	[011]
[011]	0	1	1	No Change	No Change	No Change
[100]	1	0	0	[101]	No Change	[111] ⁽²⁾
[101]	1	0	1	No Change	[100]	[111]
[110]	1	1	0	[111]	No Change	[111] ⁽²⁾
[111]	1	1	1	No Change	[110]	No Change

Notes:

1. “Set Lock” means Set Block Lock Bit command, “Clear Lock” means Clear Block Lock Bit command and “Set Lock-down” means Set Block Lock-Down Bit command.
2. When the Set Block Lock-Down Bit command is written to the unlocked block (DQ₀ = 0), the corresponding block is locked-down and automatically locked at the same time.
3. “No Change” means that the state remains unchanged after the command written.
4. In this state transitions table, assumes that F- \overline{WP} is not changed and fixed V_{IL} or V_{IH}.

5.5 Block Locking State Transitions upon $F\overline{WP}$ Transition⁽⁴⁾

Previous State	Current State				Result after $F\overline{WP}$ Transition (Next State)	
	State	$F\overline{WP}$	DQ ₁	DQ ₀	$F\overline{WP} = 0 \rightarrow 1$ ⁽¹⁾	$F\overline{WP} = 1 \rightarrow 0$ ⁽¹⁾
-	[000]	0	0	0	[100]	-
-	[001]	0	0	1	[101]	-
[110] ⁽²⁾	[011]	0	1	1	[110]	-
Other than [110] ⁽²⁾					[111]	-
-	[100]	1	0	0	-	[000]
-	[101]	1	0	1	-	[001]
-	[110]	1	1	0	-	[011] ⁽³⁾
-	[111]	1	1	1	-	[011]

Notes:

1. " $F\overline{WP} = 0 \rightarrow 1$ " means that $F\overline{WP}$ is driven to V_{IH} and " $F\overline{WP} = 1 \rightarrow 0$ " means that $F\overline{WP}$ is driven to V_{IL} .
2. State transition from the current state [011] to the next state depends on the previous state.
3. When $F\overline{WP}$ is driven to V_{IL} in [110] state, the state changes to [011] and the blocks are automatically locked.
4. In this state transitions table, assumes that lock configuration commands are not written in previous, current and next state.

6. Status Register Definition

Status Register Definition

R	R	R	R	R	R	R	R
15	14	13	12	11	10	9	8
WSMS	BESS	BEFCES	PBPS	VPPS	PBPSS	DPS	R
7	6	5	4	3	2	1	0

<p>SR.15 - SR.8 = RESERVED FOR FUTURE ENHANCEMENTS (R)</p> <p>SR.7 = WRITE STATE MACHINE STATUS (WSMS) 1 = Ready 0 = Busy</p> <p>SR.6 = BLOCK ERASE SUSPEND STATUS (BESS) 1 = Block Erase Suspended 0 = Block Erase in Progress/Completed</p> <p>SR.5 = BLOCK ERASE AND FULL CHIP ERASE STATUS (BEFCES) 1 = Error in Block Erase or Full Chip Erase 0 = Successful Block Erase or Full Chip Erase</p> <p>SR.4 = (PAGE BUFFER) PROGRAM STATUS (PBPS) 1 = Error in (Page Buffer) Program 0 = Successful (Page Buffer) Program</p> <p>SR.3 = F-V_{pp} STATUS (VPPS) 1 = F-V_{pp} LOW Detect, Operation Abort 0 = F-V_{pp} OK</p> <p>SR.2 = (PAGE BUFFER) PROGRAM SUSPEND STATUS (PBPSS) 1 = (Page Buffer) Program Suspended 0 = (Page Buffer) Program in Progress/Completed</p> <p>SR.1 = DEVICE PROTECT STATUS (DPS) 1 = Erase or Program Attempted on a Locked Block, Operation Abort 0 = Unlocked</p> <p>SR.0 = RESERVED FOR FUTURE ENHANCEMENTS (R)</p>	<p>Notes:</p> <p>Status Register indicates the status of the partition, not WSM (Write State Machine). Even if the SR.7 is "1", the WSM may be occupied by the other partition when the device is set to 2, 3 or 4 partitions configuration.</p> <p>Check SR.7 or F-RY/$\overline{\text{BY}}$ to determine block erase, full chip erase, (page buffer) program completion. SR.6 - SR.1 are invalid while SR.7= "0".</p> <p>If both SR.5 and SR.4 are "1"s after a block erase, full chip erase, page buffer program, set/clear block lock bit, set block lock-down bit or set partition configuration register attempt, an improper command sequence was entered.</p> <p>SR.3 does not provide a continuous indication of F-V_{pp} level. The WSM interrogates and indicates the F-V_{pp} level only after Block Erase, Full Chip Erase, (Page Buffer) Program command sequences. SR.3 is not guaranteed to report accurate feedback when F-V_{pp}≠V_{ppH1/2} or V_{PPLK}.</p> <p>SR.1 does not provide a continuous indication of block lock bit. The WSM interrogates the block lock bit only after Block Erase, Full Chip Erase, (Page Buffer) Program command sequences. It informs the system, depending on the attempted operation, if the block lock bit is set. Reading the block lock configuration codes after writing the Read Identifier Codes command indicates block lock bit status.</p> <p>SR.15 - SR.8 and SR.0 are reserved for future use and should be masked out when polling the status register.</p>
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Extended Status Register Definition							
R	R	R	R	R	R	R	R
15	14	13	12	11	10	9	8
SMS	R	R	R	R	R	R	R
7	6	5	4	3	2	1	0
<p>XSR.15-8 = RESERVED FOR FUTURE ENHANCEMENTS (R)</p> <p>XSR.7 = STATE MACHINE STATUS (SMS) 1 = Page Buffer Program available 0 = Page Buffer Program not available</p> <p>XSR.6-0 = RESERVED FOR FUTURE ENHANCEMENTS (R)</p>				<p>Notes:</p> <p>After issue a Page Buffer Program command (E8H), XSR.7="1" indicates that the entered command is accepted. If XSR.7 is "0", the command is not accepted and a next Page Buffer Program command (E8H) should be issued again to check if page buffer is available or not.</p> <p>XSR.15-8 and XSR.6-0 are reserved for future use and should be masked out when polling the extended status register.</p>			

Partition Configuration Register Definition							
R	R	R	R	R	PC2	PC1	PC0
15	14	13	12	11	10	9	8
R	R	R	R	R	R	R	R
7	6	5	4	3	2	1	0
<p>PCR.15-11 = RESERVED FOR FUTURE ENHANCEMENTS (R)</p> <p>PCR.10-8 = PARTITION CONFIGURATION (PC2-0)</p> <p>000 = No partitioning. Dual Work is not allowed.</p> <p>001 = Plane1-3 are merged into one partition. (default in a bottom parameter device)</p> <p>010 = Plane 0-1 and Plane2-3 are merged into one partition respectively.</p> <p>100 = Plane 0-2 are merged into one partition. (default in a top parameter device)</p> <p>011 = Plane 2-3 are merged into one partition. There are three partitions in this configuration. Dual work operation is available between any two partitions.</p> <p>110 = Plane 0-1 are merged into one partition. There are three partitions in this configuration. Dual work operation is available between any two partitions.</p> <p>101 = Plane 1-2 are merged into one partition. There are three partitions in this configuration. Dual work operation is available between any two partitions.</p>				<p>111 = There are four partitions in this configuration. Each plane corresponds to each partition respectively. Dual work operation is available between any two partitions.</p> <p>PCR.7-0 = RESERVED FOR FUTURE ENHANCEMENTS (R)</p> <p>Notes: After power-up or device reset, PCR10-8 (PC2-0) is set to "001" in a bottom parameter device and "100" in a top parameter device.</p> <p>See the table below for more details.</p> <p>PCR.15-11 and PCR.7-0 are reserved for future use and should be masked out when polling the partition configuration register.</p>			

Partition Configuration

PC2 PC1 PC0	PARTITIONING FOR DUAL WORK	PC2 PC1 PC0	PARTITIONING FOR DUAL WORK
0 0 0	<p>PARTITION0</p>	0 1 1	<p>PARTITION2 PARTITION1 PARTITION0</p>
0 0 1	<p>PARTITION1 PARTITION0</p>	1 1 0	<p>PARTITION2 PARTITION1 PARTITION0</p>
0 1 0	<p>PARTITION1 PARTITION0</p>	1 0 1	<p>PARTITION2 PARTITION1 PARTITION0</p>
1 0 0	<p>PARTITION1 PARTITION0</p>	1 1 1	<p>PARTITION3 PARTITION2 PARTITION1 PARTITION0</p>

7. Memory Map for Flash Memory

BLOCK NUMBER ADDRESS RANGE			Top Parameter				
PLANE3 (PARAMETER PLANE)	134	4K-WORD	3FF000H - 3FFFFFH	PLANE1 (UNIFORM PLANE)	63	32K-WORD	1F8000H - 1FFFFFH
	133	4K-WORD	3FE000H - 3FEFFFFH		62	32K-WORD	1F0000H - 1F7FFFFH
	132	4K-WORD	3FD000H - 3FDFFFFH		61	32K-WORD	1E8000H - 1EFFFFFH
	131	4K-WORD	3FC000H - 3FCFFFFH		60	32K-WORD	1E0000H - 1E7FFFFH
	130	4K-WORD	3FB000H - 3FBFFFFH		59	32K-WORD	1D8000H - 1DFFFFFH
	129	4K-WORD	3FA000H - 3FAFFFFH		58	32K-WORD	1D0000H - 1D7FFFFH
	128	4K-WORD	3F9000H - 3F9FFFFH		57	32K-WORD	1C8000H - 1CFFFFFH
	127	4K-WORD	3F8000H - 3F8FFFFH		56	32K-WORD	1C0000H - 1C7FFFFH
	126	32K-WORD	3F0000H - 3F7FFFFH		55	32K-WORD	1B8000H - 1BFFFFFH
	125	32K-WORD	3E8000H - 3EFFFFFH		54	32K-WORD	1B0000H - 1B7FFFFH
	124	32K-WORD	3E0000H - 3E7FFFFH		53	32K-WORD	1A8000H - 1AFFFFFH
	123	32K-WORD	3D8000H - 3DFFFFFH		52	32K-WORD	1A0000H - 1A7FFFFH
	122	32K-WORD	3D0000H - 3D7FFFFH		51	32K-WORD	198000H - 19FFFFFH
	121	32K-WORD	3C8000H - 3CFFFFFH		50	32K-WORD	190000H - 197FFFFH
	120	32K-WORD	3C0000H - 3C7FFFFH		49	32K-WORD	188000H - 18FFFFFH
	119	32K-WORD	3B8000H - 3BFFFFFH		48	32K-WORD	180000H - 187FFFFH
	118	32K-WORD	3B0000H - 3B7FFFFH		47	32K-WORD	178000H - 17FFFFFH
	117	32K-WORD	3A8000H - 3AFFFFFH		46	32K-WORD	170000H - 177FFFFH
	116	32K-WORD	3A0000H - 3A7FFFFH		45	32K-WORD	168000H - 16FFFFFH
	115	32K-WORD	398000H - 39FFFFFH		44	32K-WORD	160000H - 167FFFFH
	114	32K-WORD	390000H - 397FFFFH		43	32K-WORD	158000H - 15FFFFFH
	113	32K-WORD	388000H - 38FFFFFH		42	32K-WORD	150000H - 157FFFFH
	112	32K-WORD	380000H - 387FFFFH		41	32K-WORD	148000H - 147FFFFH
	111	32K-WORD	378000H - 377FFFFH		40	32K-WORD	140000H - 147FFFFH
	110	32K-WORD	370000H - 377FFFFH		39	32K-WORD	138000H - 137FFFFH
	109	32K-WORD	368000H - 36FFFFFH		38	32K-WORD	130000H - 137FFFFH
	108	32K-WORD	360000H - 367FFFFH		37	32K-WORD	128000H - 127FFFFH
	107	32K-WORD	358000H - 35FFFFFH		36	32K-WORD	120000H - 127FFFFH
	106	32K-WORD	350000H - 357FFFFH		35	32K-WORD	118000H - 117FFFFH
	105	32K-WORD	348000H - 347FFFFH		34	32K-WORD	110000H - 117FFFFH
	104	32K-WORD	340000H - 347FFFFH		33	32K-WORD	108000H - 107FFFFH
	103	32K-WORD	338000H - 337FFFFH		32	32K-WORD	100000H - 107FFFFH
102	32K-WORD	330000H - 337FFFFH					
101	32K-WORD	328000H - 327FFFFH					
100	32K-WORD	320000H - 327FFFFH					
99	32K-WORD	318000H - 317FFFFH					
98	32K-WORD	310000H - 317FFFFH					
97	32K-WORD	308000H - 307FFFFH					
96	32K-WORD	300000H - 307FFFFH					
PLANE2 (UNIFORM PLANE)	95	32K-WORD	2F8000H - 2FFFFFH	PLANE0 (UNIFORM PLANE)	31	32K-WORD	0F8000H - 0FFFFFH
	94	32K-WORD	2F0000H - 2F7FFFFH		30	32K-WORD	0F0000H - 0F7FFFFH
	93	32K-WORD	2E8000H - 2EFFFFFH		29	32K-WORD	0E8000H - 0EFFFFFH
	92	32K-WORD	2E0000H - 2E7FFFFH		28	32K-WORD	0E0000H - 0E7FFFFH
	91	32K-WORD	2D8000H - 2DFFFFFH		27	32K-WORD	0D8000H - 0DFFFFFH
	90	32K-WORD	2D0000H - 2D7FFFFH		26	32K-WORD	0D0000H - 0D7FFFFH
	89	32K-WORD	2C8000H - 2CFFFFFH		25	32K-WORD	0C8000H - 0CFFFFFH
	88	32K-WORD	2C0000H - 2C7FFFFH		24	32K-WORD	0C0000H - 0C7FFFFH
	87	32K-WORD	2B8000H - 2BFFFFFH		23	32K-WORD	0B8000H - 0BFFFFFH
	86	32K-WORD	2B0000H - 2B7FFFFH		22	32K-WORD	0B0000H - 0B7FFFFH
	85	32K-WORD	2A8000H - 2AFFFFFH		21	32K-WORD	0A8000H - 0AFFFFFH
	84	32K-WORD	2A0000H - 2A7FFFFH		20	32K-WORD	0A0000H - 0A7FFFFH
	83	32K-WORD	298000H - 29FFFFFH		19	32K-WORD	098000H - 09FFFFFH
	82	32K-WORD	290000H - 297FFFFH		18	32K-WORD	090000H - 097FFFFH
	81	32K-WORD	288000H - 28FFFFFH		17	32K-WORD	088000H - 08FFFFFH
	80	32K-WORD	280000H - 287FFFFH		16	32K-WORD	080000H - 087FFFFH
	79	32K-WORD	278000H - 277FFFFH		15	32K-WORD	078000H - 077FFFFH
	78	32K-WORD	270000H - 277FFFFH		14	32K-WORD	070000H - 077FFFFH
	77	32K-WORD	268000H - 267FFFFH		13	32K-WORD	068000H - 067FFFFH
	76	32K-WORD	260000H - 267FFFFH		12	32K-WORD	060000H - 067FFFFH
	75	32K-WORD	258000H - 257FFFFH		11	32K-WORD	058000H - 057FFFFH
	74	32K-WORD	250000H - 257FFFFH		10	32K-WORD	050000H - 057FFFFH
	73	32K-WORD	248000H - 247FFFFH		9	32K-WORD	048000H - 047FFFFH
	72	32K-WORD	240000H - 247FFFFH		8	32K-WORD	040000H - 047FFFFH
	71	32K-WORD	238000H - 237FFFFH		7	32K-WORD	038000H - 037FFFFH
	70	32K-WORD	230000H - 237FFFFH		6	32K-WORD	030000H - 037FFFFH
	69	32K-WORD	228000H - 227FFFFH		5	32K-WORD	028000H - 027FFFFH
	68	32K-WORD	220000H - 227FFFFH		4	32K-WORD	020000H - 027FFFFH
	67	32K-WORD	218000H - 217FFFFH		3	32K-WORD	018000H - 017FFFFH
	66	32K-WORD	210000H - 217FFFFH		2	32K-WORD	010000H - 017FFFFH
	65	32K-WORD	208000H - 207FFFFH		1	32K-WORD	008000H - 007FFFFH
	64	32K-WORD	200000H - 207FFFFH		0	32K-WORD	000000H - 007FFFFH

8. Absolute Maximum Ratings

Symbol	Parameter	Notes	Ratings	Unit
V_{CC}	Supply voltage	1,2	-0.2 to +3.6	V
V_{IN}	Input voltage	1,2,3,4	-0.5 to $V_{CC} + 0.3$	V
T_A	Operating temperature		-25 to +85	°C
T_{STG}	Storage temperature		-65 to +125	°C
$F-V_{PP}$	F- V_{PP} voltage	1,3,5	-0.2 to +12.6	V

Notes:

1. The maximum applicable voltage on any pins with respect to GND.
2. Except F- V_{PP} .
3. -1.0V undershoot is allowed when the pulse width is less than 5 nsec.
4. V_{IN} should not be over $V_{CC} + 0.3V$.
5. Applying 12V \pm 0.3V to F- V_{PP} during erase/write can only be done for a maximum of 1000 cycles on each block. F- V_{PP} may be connected to 12V \pm 0.3V for total of 80 hours maximum. +13.0V overshoot is allowed when the pulse width is less than 20 nsec.

9. Recommended DC Operating Conditions

($T_A = -25^\circ\text{C}$ to $+85^\circ\text{C}$)

Symbol	Parameter	Notes	Min.	Typ.	Max.	Unit
$F-V_{CC}$	Supply Voltage		2.7	3.0	3.3	V
$S-V_{CC}$	Supply Voltage		2.7		3.1	V
V_{IH}	Input Voltage		$V_{CC} - 0.3$ ⁽²⁾		$V_{CC} + 0.3$ ⁽¹⁾	V
V_{IL}	Input Voltage		-0.3		0.3	V

Notes:

1. V_{CC} is the lower of F- V_{CC} or S- V_{CC} .
2. V_{CC} is the higher of F- V_{CC} or S- V_{CC} .

10. Pin Capacitance⁽¹⁾

($T_A = 25^\circ\text{C}$, $f = 1\text{MHz}$)

Symbol	Parameter	Notes	Min.	Typ.	Max.	Unit	Condition
C_{IN}	Input capacitance				15	pF	$V_{IN} = 0V$
$C_{I/O}$	I/O capacitance				25	pF	$V_{I/O} = 0V$

Note:

1. Sampled but not 100% tested.

11. DC Electrical Characteristics⁽¹⁾

DC Electrical Characteristics

(T_A = -25°C to +85°C, F-V_{CC} = 2.7V to 3.3V, S-V_{CC} = 2.7V to 3.1V)

Symbol	Parameter	Notes	Min.	Typ.	Max.	Unit	Test Conditions
I _{LI}	Input Load Current				±1.5	μA	V _{IN} = V _{CC} or GND
I _{LO}	Output Leakage Current				±1.5	μA	V _{OUT} = V _{CC} or GND
I _{CCS}	F-V _{CC} Standby Current	2		4	20	μA	F-V _{CC} = F-V _{CC} Max., F- \overline{CE} = F-R \overline{ST} = F-V _{CC} ±0.2V, F- \overline{WP} = F-V _{CC} or GND
I _{CCAS}	F-V _{CC} Automatic Power Savings Current	2,5		4	20	μA	F-V _{CC} = F-V _{CC} Max., F- \overline{CE} = GND ±0.2V, F- \overline{WP} = F-V _{CC} or GND
I _{CCD}	F-V _{CC} Reset Power-Down Current	2		4	20	μA	F-R \overline{ST} = GND ±0.2V I _{OUT} (F-RY/ \overline{BY}) = 0mA
I _{CCR}	Average F-V _{CC} Read Current Normal Mode	2,10		15	25	mA	F-V _{CC} = F-V _{CC} Max., F- \overline{CE} = V _{IL} , F- \overline{OE} = V _{IH} , f = 5MHz I _{OUT} = 0mA
	Average F-V _{CC} Read Current Page Mode	8 Word Read	2,10	5	10	mA	
I _{CCW}	F-V _{CC} (Page Buffer) Program Current	2,6,10		20	60	mA	F-V _{PP} = V _{PPH1}
		2,6,10		10	20	mA	F-V _{PP} = V _{PPH2}
I _{CCCE}	F-V _{CC} Block Erase, Full Chip Erase Current	2,6,10		10	30	mA	F-V _{PP} = V _{PPH1}
		2,6,10		10	30	mA	F-V _{PP} = V _{PPH2}
I _{CCWS} I _{CCES}	F-V _{CC} (Page Buffer) Program or Block Erase Suspend Current	2,3,10		10	200	μA	F- \overline{CE} = V _{IH}
I _{PPS} I _{PPR}	F-V _{PP} Standby or Read Current	2,7,10		2	5	μA	F-V _{PP} ≤ F-V _{CC}
I _{PPW}	F-V _{PP} (Page Buffer) Program Current	2,6,7,10		2	5	μA	F-V _{PP} = V _{PPH1}
		2,6,7,10		10	30	mA	F-V _{PP} = V _{PPH2}
I _{PPPE}	F-V _{PP} Block Erase, Full Chip Erase Current	2,6,7,10		2	5	μA	F-V _{PP} = V _{PPH1}
		2,6,7,10		5	15	mA	F-V _{PP} = V _{PPH2}
I _{PPWS}	F-V _{PP} (Page Buffer) Program Suspend Current	2,7,10		2	5	μA	F-V _{PP} = V _{PPH1}
		2,7,10		10	200	μA	F-V _{PP} = V _{PPH2}
I _{PPES}	F-V _{PP} Block Erase Suspend Current	2,7,10		2	5	μA	F-V _{PP} = V _{PPH1}
		2,7,10		10	200	μA	F-V _{PP} = V _{PPH2}

DC Electrical Characteristics (Continue)

($T_A = -25^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $F\text{-}V_{CC} = 2.7\text{V}$ to 3.3V , $S\text{-}V_{CC} = 2.7\text{V}$ to 3.1V)

Symbol	Parameter	Notes	Min.	Typ.	Max.	Unit	Conditions
I_{SB}	S- V_{CC} Standby Current	8			80	μA	$S\text{-}\overline{CE}_1 \geq S\text{-}V_{CC} - 0.2\text{V}$
I_{SLP}	S- V_{CC} Sleep Mode Current	9			15	μA	$S\text{-}CE_2 \leq 0.2\text{V}$
I_{CC1}	S- V_{CC} Operation Current				20	mA	$t_{CYCLE} = \text{Min.}, I_{I/O} = 0\text{mA}$
I_{CC2}	S- V_{CC} Operation Current				3	mA	$t_{CYCLE} = 1\mu\text{s}, I_{I/O} = 0\text{mA}$
V_{IL}	Input Low Voltage	6	-0.3		0.3	V	
V_{IH}	Input High Voltage	6	V_{CC} -0.3		V_{CC} +0.3	V	
V_{OL}	Output Low Voltage	6			0.3	V	$I_{OL} = 0.5\text{mA}$
V_{OH}	Output High Voltage	6	V_{CC} -0.3			V	$I_{OH} = -0.5\text{mA}$
V_{PPLK}	F- V_{PP} Lockout during Normal Operations	4,6,7			0.4	V	
V_{PPH1}	F- V_{PP} during Block Erase, Full Chip Erase,(PageBuffer) Program	7	1.65	3	3.3	V	
V_{PPH2}	F- V_{PP} during Block Erase, (PageBuffer) Program	7	11.7	12	12.3	V	
V_{LKO}	F- V_{CC} Lockout Voltage		1.5			V	

Notes:

- V_{CC} includes both F- V_{CC} and S- V_{CC} .
- All currents are in RMS unless otherwise noted. Typical values are the reference values at $V_{CC} = 3.0\text{V}$ and $T_A = +25^{\circ}\text{C}$ unless V_{CC} is specified.
- I_{CCWS} and I_{CCES} are specified with the device de-selected. If read or (page buffer) program while in block erase suspend mode, the device's current draw is the sum of I_{CCWS} or I_{CCES} and I_{CCR} or I_{CCW} , respectively.
- Block erase, full chip erase, (page buffer) program are inhibited when $F\text{-}V_{PP} \leq V_{PPLK}$, and not guaranteed in the range between V_{PPLK} (max.) and V_{PPH1} (min.), between V_{PPH1} (max.) and V_{PPH2} (min.) and above V_{PPH2} (max.).
- The Automatic Power Savings (APS) feature automatically places the device in power save mode after read cycle completion. Standard address access timings (t_{AVQV}) provide new data when addresses are changed.
- Sampled, not 100% tested.
- F- V_{PP} is not used for power supply pin. With $F\text{-}V_{PP} \leq V_{PPLK}$, block erase, full chip erase, (page buffer) program cannot be executed and should not be attempted.
Applying $12\text{V} \pm 0.3\text{V}$ to F- V_{PP} provides fast erasing or fast programming mode. In this mode, F- V_{PP} is power supply pin and supplies the memory cell current for block erasing and (page buffer) programming. Use similar power supply trace widths and layout considerations given to the V_{CC} power bus.
Applying $12\text{V} \pm 0.3\text{V}$ to F- V_{PP} during erase/program can only be done for a maximum of 1000 cycles on each block. F- V_{PP} may be connected to $12\text{V} \pm 0.3\text{V}$ for a total of 80 hours maximum.
- Memory cell data is held. ($S\text{-}CE_2 = "V_{IH}"$)
- Memory cell data is not held. ($S\text{-}CE_2 = "V_{IL}"$)
- The operating current in dual work is the sum of the operating current (read, erase, program) in each plane.

12. AC Electrical Characteristics for Flash Memory

12.1 AC Test Conditions

Input pulse level	0 V to 2.7 V
Input rise and fall time	5 ns
Input and Output timing Ref. level	1.35 V
Output load	1TTL + C _L (50pF)

12.2 Read Cycle

(T_A = -25°C to +85°C, F-V_{CC} = 2.7V to 3.3V)

Symbol	Parameter	Notes	Min.	Max.	Unit
t _{AVAV}	Read Cycle Time		85		ns
t _{AVQV}	Address to Output Delay			85	ns
t _{ELQV}	F- $\overline{\text{CE}}$ to Output Delay	2		85	ns
t _{APA}	Page Address Access Time			35	ns
t _{GLQV}	F- $\overline{\text{OE}}$ to Output Delay	2		20	ns
t _{PHQV}	F- $\overline{\text{RST}}$ High to Output Delay			150	ns
t _{EHQZ} , t _{GHQZ}	F- $\overline{\text{CE}}$ or F- $\overline{\text{OE}}$ to Output in High-Z, Whichever Occurs First	1		20	ns
t _{ELQX}	F- $\overline{\text{CE}}$ to Output in Low-Z	1	0		ns
t _{GLQX}	F- $\overline{\text{OE}}$ to Output in Low-Z	1	0		ns
t _{OH}	Output Hold from First Occurring Address, F- $\overline{\text{CE}}$ or F- $\overline{\text{OE}}$ change	1	0		ns

Notes:

1. Sampled, not 100% tested.
2. F- $\overline{\text{OE}}$ may be delayed up to t_{ELQV} - t_{GLQV} after the falling edge of F- $\overline{\text{CE}}$ without impact to t_{ELQV}.

12.3 Write Cycle (F- \overline{WE} / F- \overline{CE} Controlled)^(1,2)

(T_A = -25°C to +85°C, F-V_{CC} = 2.7V to 3.3V)

Symbol	Parameter	Notes	Min.	Max.	Unit
t _{AVAV}	Write Cycle Time		85		ns
t _{PHWL} (t _{PHL})	F- \overline{RST} High Recovery to F- \overline{WE} (F- \overline{CE}) Going Low	3	150		ns
t _{ELWL} (t _{WLEL})	F- \overline{CE} (F- \overline{WE}) Setup to F- \overline{WE} (F- \overline{CE}) Going Low	4	0		ns
t _{WLWH} (t _{ELEH})	F- \overline{WE} (F- \overline{CE}) Pulse Width	4	60		ns
t _{DVWH} (t _{DVEH})	Data Setup to F- \overline{WE} (F- \overline{CE}) Going High	8	40		ns
t _{AVWH} (t _{AVEH})	Address Setup to F- \overline{WE} (F- \overline{CE}) Going High	8	50		ns
t _{WHEH} (t _{EHWH})	F- \overline{CE} (F- \overline{WE}) Hold from F- \overline{WE} (F- \overline{CE}) High		0		ns
t _{WHDX} (t _{EHDX})	Data Hold from F- \overline{WE} (F- \overline{CE}) High		0		ns
t _{WHAX} (t _{EHAX})	Address Hold from F- \overline{WE} (F- \overline{CE}) High		0		ns
t _{WHWL} (t _{EHEL})	F- \overline{WE} (F- \overline{CE}) Pulse Width High	5	30		ns
t _{SHWH} (t _{SHEH})	F- \overline{WP} High Setup to F- \overline{WE} (F- \overline{CE}) Going High	3	0		ns
t _{VVWH} (t _{VVEH})	F-V _{PP} Setup to F- \overline{WE} (F- \overline{CE}) Going High	3	200		ns
t _{WHGL} (t _{EHGL})	Write Recovery before Read		30		ns
t _{QVSL}	F- \overline{WP} High Hold from Valid SRD, F-RY/ \overline{BY} High-Z	3, 6	0		ns
t _{QVVL}	F-V _{PP} Hold from Valid SRD, F-RY/ \overline{BY} High-Z	3, 6	0		ns
t _{WHR0} (t _{EHR0})	F- \overline{WE} (F- \overline{CE}) High to SR.7 Going "0"	3, 7		t _{AVQV} +40	ns
t _{WHRL} (t _{EHRL})	F- \overline{WE} (F- \overline{CE}) High to F-RY/ \overline{BY} Going Low	3		100	ns

Notes:

1. The timing characteristics for reading the status register during block erase, full chip erase, (page buffer) program operations are the same as during read-only operations. See the AC Characteristics for read cycle.
2. A write operation can be initiated and terminated with either F- \overline{CE} or F- \overline{WE} .
3. Sampled, not 100% tested.
4. Write pulse width (t_{WP}) is defined from the falling edge of F- \overline{CE} or F- \overline{WE} (whichever goes low last) to the rising edge of F- \overline{CE} or F- \overline{WE} (whichever goes high first). Hence, t_{WP}=t_{WLWH}=t_{ELEH}=t_{WLEH}=t_{ELWH}.
5. Write pulse width high (t_{WPH}) is defined from the rising edge of F- \overline{CE} or F- \overline{WE} (whichever goes high first) to the falling edge of F- \overline{CE} or F- \overline{WE} (whichever goes low last). Hence, t_{WPH}=t_{WHWL}=t_{EHEL}=t_{WHEL}=t_{EHWL}.
6. F-V_{PP} should be held at F-V_{PP}=V_{PPH1/2} until determination of block erase, (page buffer) program success (SR.1/3/4/5=0) and held at F-V_{PP}=V_{PPH1} until determination of full chip erase success (SR.1/3/5=0).
7. t_{WHR0} (t_{EHR0}) after the Read Query or Read Identifier Codes command=t_{AVQV}+100ns.
8. See 5.1 Command Definitions for valid address and data for block erase, full chip erase, (page buffer) program or lock bit configuration.

12.4 Block Erase, Full Chip Erase, (Page Buffer) Program Performance⁽³⁾

(T_A = -25°C to +85°C, F-V_{CC} = 2.7V to 3.3V)

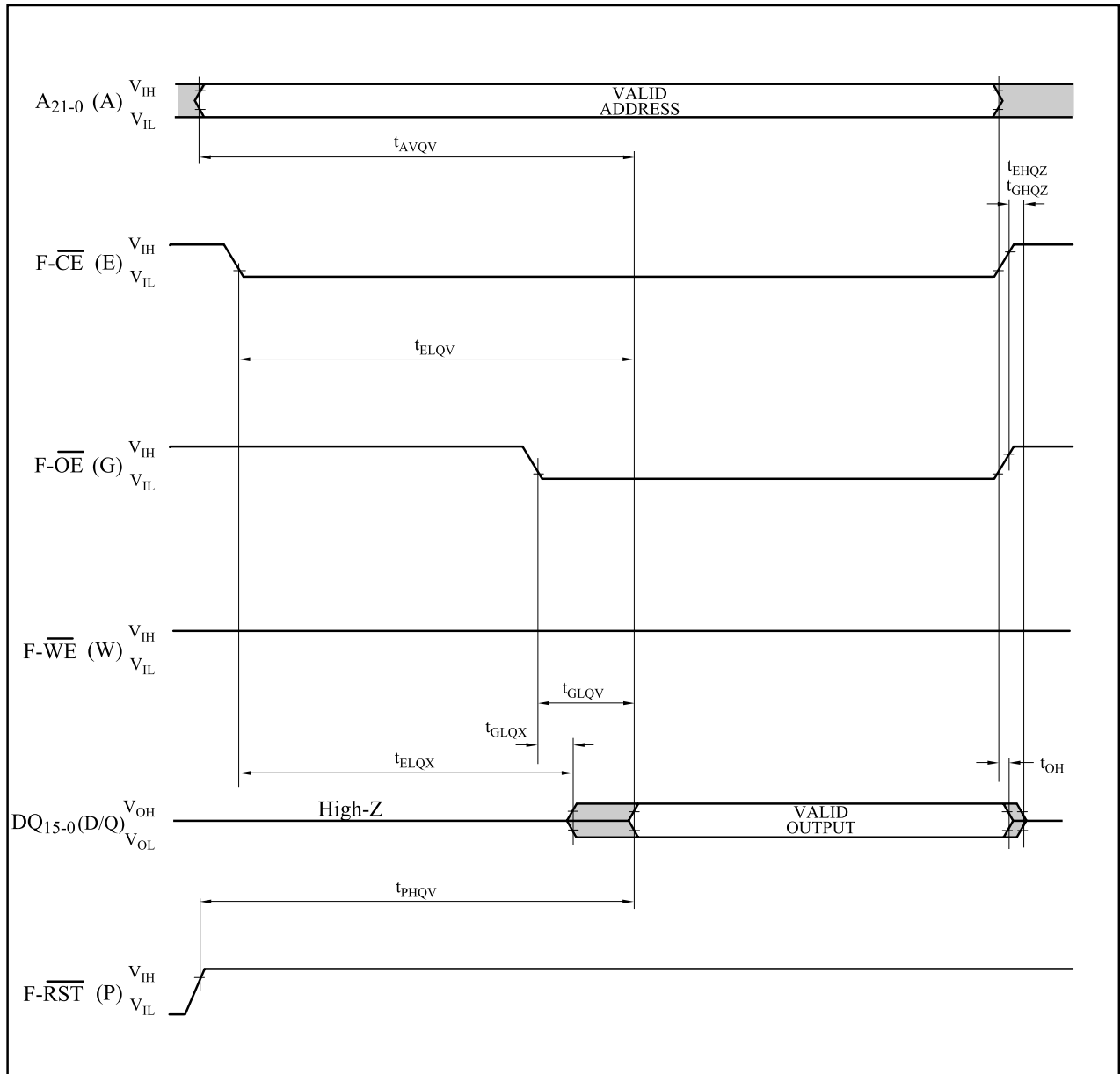
Symbol	Parameter	Notes	Page Buffer Command is Used or not Used	F-V _{PP} =V _{PPH1} (In System)			F-V _{PP} =V _{PPH2} (In Manufacturing)			Unit
				Min.	Typ. ⁽¹⁾	Max. ⁽²⁾	Min.	Typ. ⁽¹⁾	Max. ⁽²⁾	
t _{WPB}	4K-Word Parameter Block Program Time	2	Not Used		0.05	0.3		0.04	0.12	s
		2	Used		0.03	0.12		0.02	0.06	s
t _{WMB}	32K-Word Main Block Program Time	2	Not Used		0.38	2.4		0.31	1	s
		2	Used		0.24	1		0.17	0.5	s
t _{WHQV1} / t _{EHQV1}	Word Program Time	2	Not Used		11	200		9	185	μs
		2	Used		7	100		5	90	μs
t _{WHQV2} / t _{EHQV2}	4K-Word Parameter Block Erase Time	2	-		0.3	4		0.2	4	s
t _{WHQV3} / t _{EHQV3}	32K-Word Main Block Erase Time	2	-		0.6	5		0.5	5	s
	Full Chip Erase Time	2			80	700				s
t _{WHRH1} / t _{EHRH1}	(Page Buffer) Program Suspend Latency Time to Read	4	-		5	10		5	10	μs
t _{WHRH2} / t _{EHRH2}	Block Erase Suspend Latency Time to Read	4	-		5	20		5	20	μs
t _{ERES}	Latency Time from Block Erase Resume Command to Block Erase Suspend Command	5	-	500			500			μs

Notes:

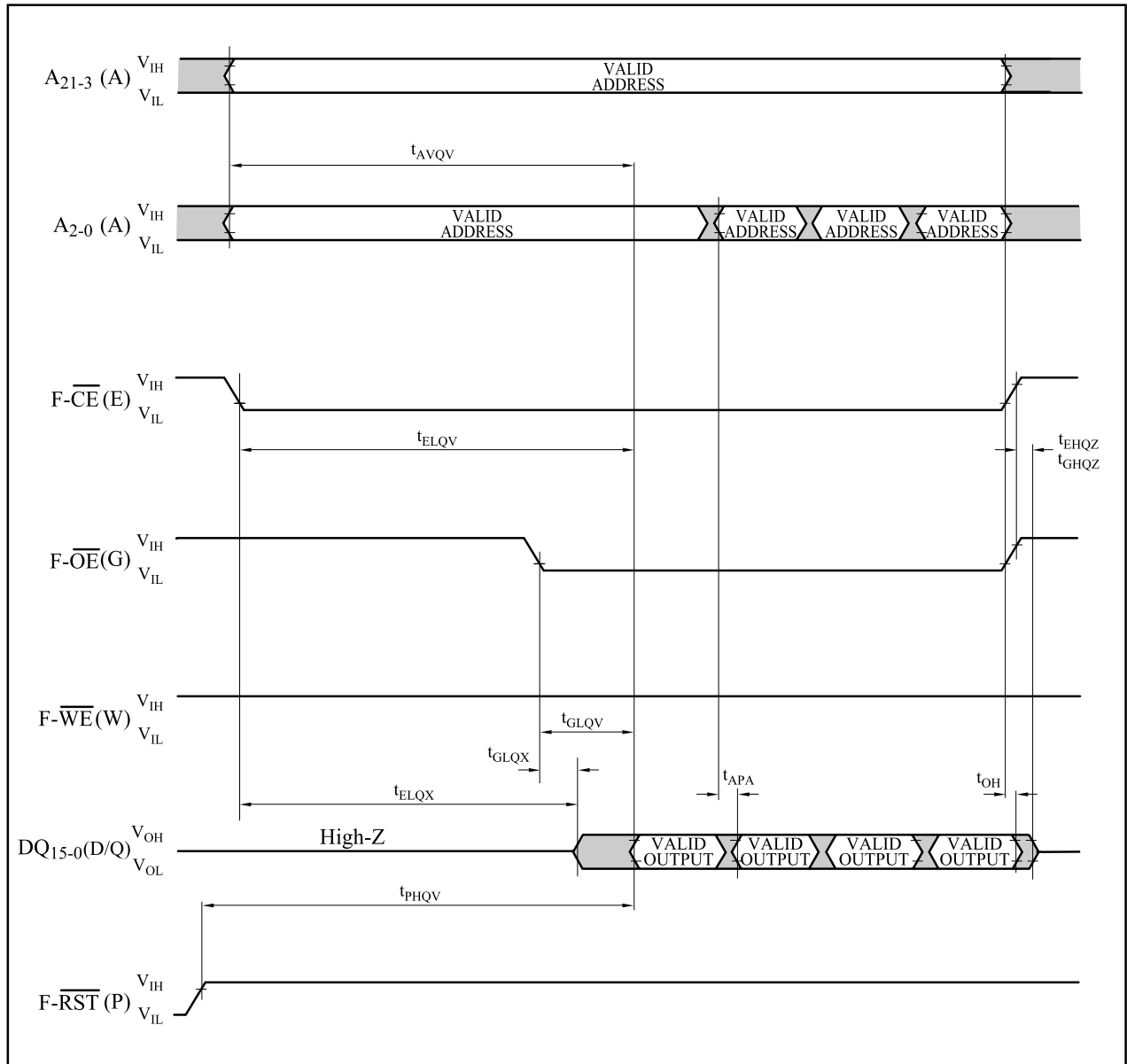
1. Typical values measured at F-V_{CC} = 3.0V, F-V_{PP} = 3.0V or 12V, and T_A = +25°C. Assumes corresponding lock bits are not set. Subject to change based on device characterization.
2. Excludes external system-level overhead.
3. Sampled, but not 100% tested.
4. A latency time is required from writing suspend command (F- \overline{WE} or F- \overline{CE} going high) until SR.7 going "1" or F-RY/ \overline{BY} going High-Z.
5. If the interval time from a Block Erase Resume command to a subsequent Block Erase Suspend command is shorter than t_{ERES} and its sequence is repeated, the block erase operation may not be finished.

12.5 Flash Memory AC Characteristics Timing Chart

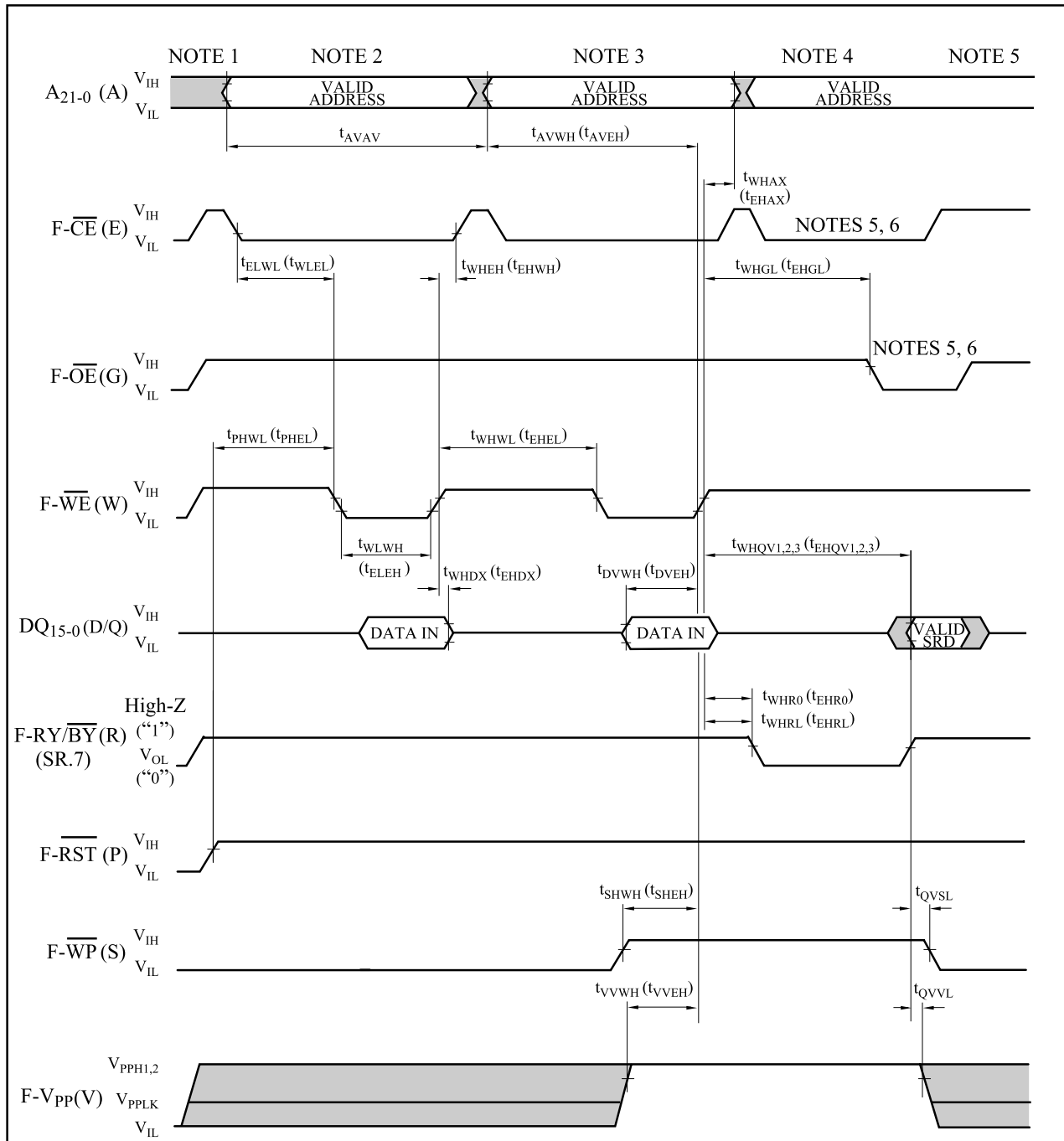
AC Waveform for Single Asynchronous Read Operations from Status Register, Identifier Codes or Query Code



AC Waveform for Asynchronous Page Mode Read Operations from Main Blocks or Parameter Blocks



AC Waveform for Write Operations(F- \overline{WE} / F- \overline{CE} Controlled)



Notes:

1. F-VCC power-up and standby.
2. Write each first cycle command.
3. Write each second cycle command or valid address and data.
4. Automated erase or program delay.
5. Read status register data.
6. For read operation, F- \overline{OE} and F- \overline{CE} must be driven active, and F- \overline{WE} de-asserted.

12.6 Reset Operations

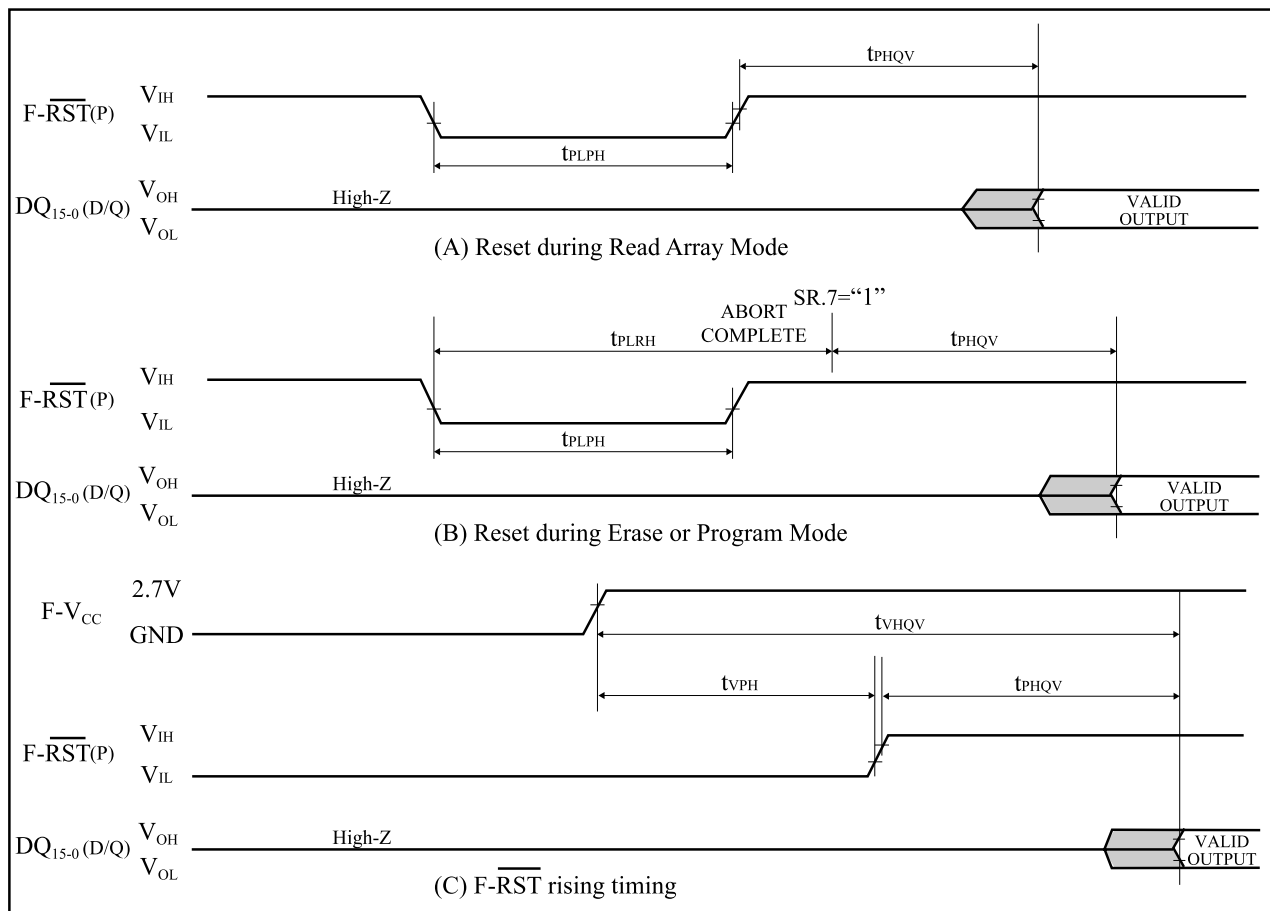
($T_A = -25^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $F\text{-}V_{CC} = 2.7\text{V}$ to 3.3V)

Symbol	Parameter	Notes	Min.	Max.	Unit
t_{PLPH}	$F\text{-}\overline{\text{RST}}$ Low to Reset during Read ($F\text{-}\overline{\text{RST}}$ should be low during power-up.)	1, 2, 3	100		ns
t_{PLRH}	$F\text{-}\overline{\text{RST}}$ Low to Reset during Erase or Program	1, 3, 4		22	μs
t_{VPH}	$F\text{-}V_{CC}$ 2.7V to $F\text{-}\overline{\text{RST}}$ High	1, 3, 5	100		ns
t_{VHQV}	$F\text{-}V_{CC}$ 2.7V to Output Delay	3		1	ms

Notes:

1. A reset time, t_{PHQV} , is required from the later of SR.7 ($F\text{-}\overline{\text{RY}}/\overline{\text{BY}}$) going "1" (High-Z) or $F\text{-}\overline{\text{RST}}$ going high until outputs are valid. See the AC Characteristics - read cycle for t_{PHQV} .
2. t_{PLPH} is $<100\text{ns}$ the device may still reset but this is not guaranteed.
3. Sampled, not 100% tested.
4. If $F\text{-}\overline{\text{RST}}$ asserted while a block erase, full chip erase or (page buffer) program operation is not executing, the reset will complete within 100ns.
5. When the device power-up, holding $F\text{-}\overline{\text{RST}}$ low minimum 100ns is required after $F\text{-}V_{CC}$ has been in predefined range and also has been in stable there.

AC Waveform for Reset Operation



13. AC Electrical Characteristic for Smartcombo RAM

13.1 AC Test Conditions

Input pulse level	0.3 V to $V_{CC} - 0.3$ V
Input rise and fall time	3 ns
Input and Output timing Ref. level	$1/2 V_{CC}$
Output load	1TTL + C_L (50pF) ⁽¹⁾

Note:

1. Including scope and socket capacitance.

13.2 Read Cycle ^(1,2,3)

($T_A = -25^\circ\text{C}$ to $+85^\circ\text{C}$, $S-V_{CC} = 2.7\text{V}$ to 3.1V)

Symbol	Parameter	Notes	Min.	Max.	Unit
t_{RC}	Read Cycle Time		85	32,000	ns
t_{AA}	Address Access Time			85	ns
t_{ACE}	Chip Enable Access Time			85	ns
t_{OE}	Output Enable to Output Valid			40	ns
t_{BE}	Byte Enable Access Time			40	ns
t_{ASC}	Address Setup to $S-\overline{CE}_1$ Low		0		ns
t_{AHC}	Address Hold to $S-\overline{CE}_1$ High		0		ns
t_{CIH}	$S-\overline{CE}_1$ High Pulse Width		30		ns
t_{CLZ}	$S-\overline{CE}_1$ Low to Output Active		0		ns
t_{CHZ}	$S-\overline{CE}_1$ High to Output in High-Z			30	ns
t_{BLZ}	$S-\overline{UB}$ or $S-\overline{LB}$ Low to Output Active		0		ns
t_{BHZ}	$S-\overline{UB}$ or $S-\overline{LB}$ High to Output in High-Z			30	ns
t_{OLZ}	$S-\overline{OE}$ Low to Output Active		0		ns
t_{OHZ}	$S-\overline{OE}$ High to Output in High-Z			30	ns
t_{OH}	Output Hold from Address Change		5		ns

Notes:

It is possible to control data width by $S-\overline{LB}$ and $S-\overline{UB}$ pins.

1. Reading data from lower byte
Data can be read when the address is set while holding $S-\overline{CE}_1 = \text{Low}$, $S-\text{CE}_2 = \text{High}$, $S-\overline{OE} = \text{Low}$, $S-\overline{WE} = \text{High}$ and $S-\overline{LB} = \text{Low}$.
2. Reading data from upper byte
Data can be read when the address is set while holding $S-\overline{CE}_1 = \text{Low}$, $S-\text{CE}_2 = \text{High}$, $S-\overline{OE} = \text{Low}$, $S-\overline{WE} = \text{High}$ and $S-\overline{UB} = \text{Low}$.
3. Reading data from both bytes
Data can be read when the address is set while holding $S-\overline{CE}_1 = \text{Low}$, $S-\text{CE}_2 = \text{High}$, $S-\overline{OE} = \text{Low}$, $S-\overline{WE} = \text{High}$, $S-\overline{LB} = \text{Low}$ and $S-\overline{UB} = \text{Low}$.

13.3 Write Cycle ^(1,2,3,4,5,6,7,8)

(T_A = -25°C to +85°C, S-V_{CC} = 2.7V to 3.1V)

Symbol	Parameter	Notes	Min.	Max.	Unit
t _{WC}	Write Cycle Time		85	32,000	ns
t _{CW}	Chip Enable to End of Write		70		ns
t _{ASC}	Address Setup to S- \overline{CE}_1 Low		0		ns
t _{AHC}	Address Hold to S- \overline{CE}_1 High		0		ns
t _{C1H}	S- \overline{CE}_1 High Pulse Width		30		ns
t _{AW}	Address Valid to End of Write		70		ns
t _{AS}	Address Setup Time		0		ns
t _{WP}	Write Pulse Width		40		ns
t _{BW}	Byte Select Time		70		ns
t _{WR}	Write Recovery Time		0		ns
t _{DW}	Input Data Setup Time		35		ns
t _{DH}	Input Data Hold Time		0		ns
t _{OW}	S- \overline{WE} High to Output Active		5		ns
t _{WHZ}	S- \overline{WE} Low to Output in High-Z			30	ns

Notes:

1. Writing data into lower byte (S- \overline{WE} controlled)
 - 1) Data can be written by adding Low pulse into S- \overline{WE} when the address is set while holding S- \overline{CE}_1 = Low, S-CE₂ = High, S- \overline{LB} = Low and S- \overline{UB} = High.
 - 2) The data on lower byte are latched up into the memory cell during S- \overline{WE} = Low and S- \overline{LB} = Low.
2. Writing data into lower byte (S- \overline{LB} controlled)
 - 1) Data can be written by adding Low pulse into S- \overline{LB} when the address is set while holding S- \overline{CE}_1 = Low, S-CE₂ = High, S- \overline{UB} = High and S- \overline{WE} = Low.
 - 2) The data on lower byte are latched up into memory cell during S- \overline{WE} = Low and S- \overline{LB} = Low.
3. Writing data into upper byte (S- \overline{WE} controlled)
 - 1) Data can be written by adding Low pulse into S- \overline{WE} when the address is set while holding S- \overline{CE}_1 = Low, S-CE₂ = High, S- \overline{LB} = High and S- \overline{UB} = Low.
 - 2) The data on upper byte are latched up into the memory cell during S- \overline{WE} = Low and S- \overline{UB} = Low.
4. Writing data into upper byte (S- \overline{UB} controlled)
 - 1) Data can be written by adding Low pulse S- \overline{UB} when the address is set while holding S- \overline{CE}_1 = Low, S-CE₂ = High, S- \overline{LB} = High and S- \overline{WE} = Low.
 - 2) The data on upper byte are latched up into the memory cell during S- \overline{WE} = Low and S- \overline{UB} = Low.
5. Writing data into both byte (S- \overline{WE} controlled)
 - 1) Data can be written by adding Low pulse into S- \overline{WE} when the address is set while holding S- \overline{CE}_1 = Low, S-CE₂ = High, S- \overline{LB} = Low and S- \overline{UB} = Low.
 - 2) The data are latched up into the memory cell during S- \overline{WE} = Low, S- \overline{LB} = Low and S- \overline{UB} = Low.
6. Writing data into both byte (S- \overline{LB} , S- \overline{UB} controlled)
 - 1) Data can be written by adding Low pulse into S- \overline{LB} and S- \overline{UB} when the address is set while holding S- \overline{CE}_1 = Low, S-CE₂ = High and S- \overline{WE} = Low.
 - 2) The data are latched up into the memory cell during S- \overline{WE} = Low, S- \overline{LB} = Low and S- \overline{UB} = Low
7. Read or write with using both S- \overline{LB} and S- \overline{UB} , the timing edge of S- \overline{LB} and S- \overline{UB} must be same.
8. While DQ pins are in the output state, the data that is opposite to the output data should not be given.

13.4 Power Up Timing

 $(T_A = -25^{\circ}\text{C to } +85^{\circ}\text{C, S-V}_{CC} = 2.7\text{V to } 3.1\text{V})$

Symbol	Parameter	Notes	Min.	Max.	Unit
t_{SHU}	$\overline{\text{S-CE}}_1$, S-CE ₂ Setup Time after Power Up		0		ns
t_{HPU}	Standby Hold Time after Power Up		300		μs

13.5 Sleep Mode Timing⁽¹⁾ $(T_A = -25^{\circ}\text{C to } +85^{\circ}\text{C, S-V}_{CC} = 2.7\text{V to } 3.1\text{V})$

Symbol	Parameter	Notes	Min.	Max.	Unit
t_{SSP}	$\overline{\text{S-CE}}_1$ High Setup Time for Sleep Mode Entry		0		ns
t_{SHP}	$\overline{\text{S-CE}}_1$ High Hold Time before Sleep Mode Exit		0		ns
t_{C2LP}	S-CE ₂ Low Pulse Width		30		ns
t_{HPD}	$\overline{\text{S-CE}}_1$ High Hold Time after Sleep Mode Exit		300		μs

Note:

1. When S-CE₂ is low, the device will be in the Sleep Mode. In this case, an internal refresh stops and the data might be lost.

13.6 Address Skew Timing

 $(T_A = -25^{\circ}\text{C to } +85^{\circ}\text{C, S-V}_{CC} = 2.7\text{V to } 3.1\text{V})$

Symbol	Parameter	Notes	Min.	Max.	Unit
t_{SKEW}	Maximum Address Skew			10	ns

13.7 Data Retention Timing⁽¹⁾ $(T_A = -25^{\circ}\text{C to } +85^{\circ}\text{C, S-V}_{CC} = 2.7\text{V to } 3.1\text{V})$

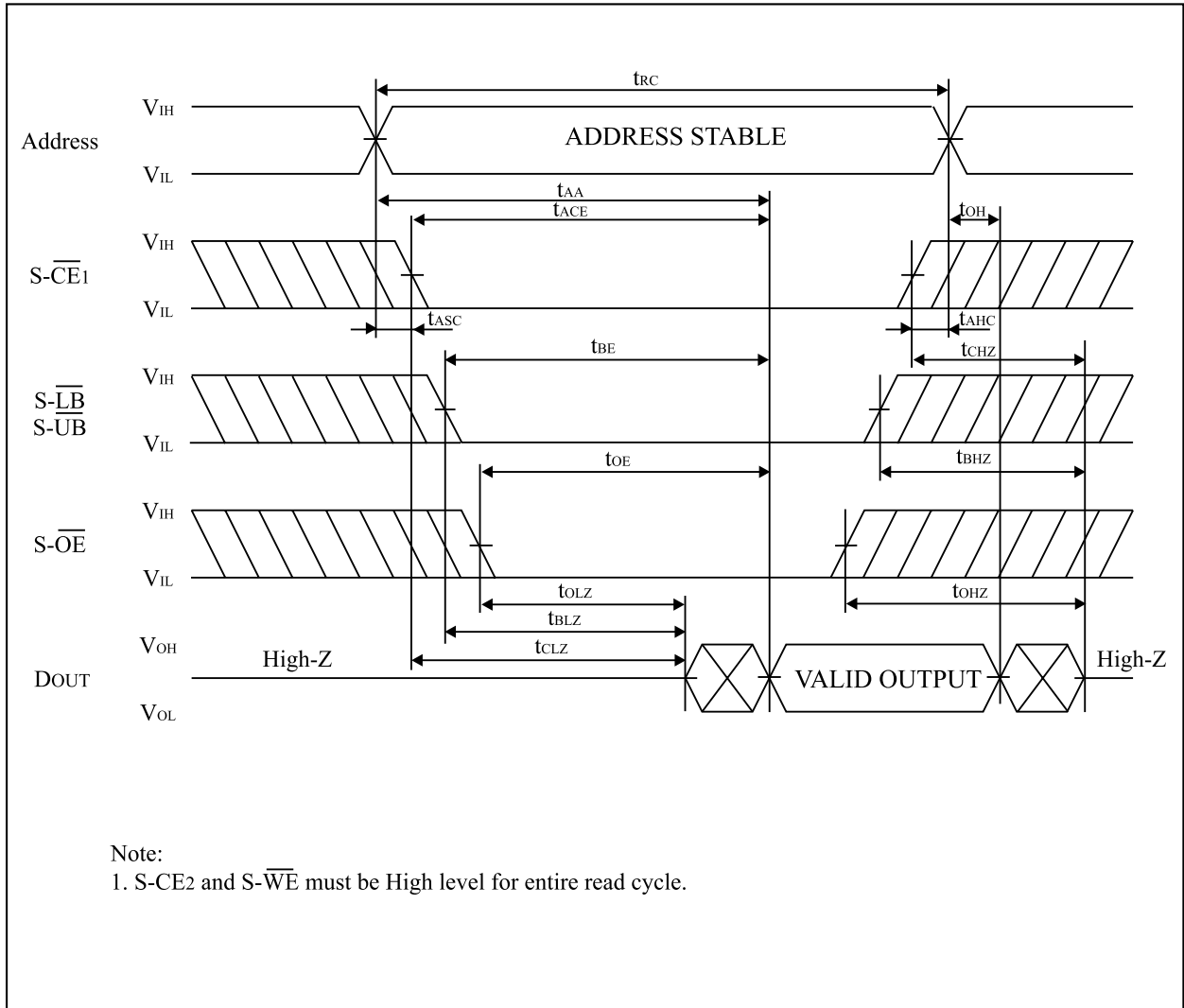
Symbol	Parameter	Notes	Min.	Max.	Unit
t_{BAH}	Address Hold Time during Active		85	32,000	ns
t_{CSH}	$\overline{\text{S-CE}}_1$ Low Hold Time for Address Fix		85	32,000	ns

Note:

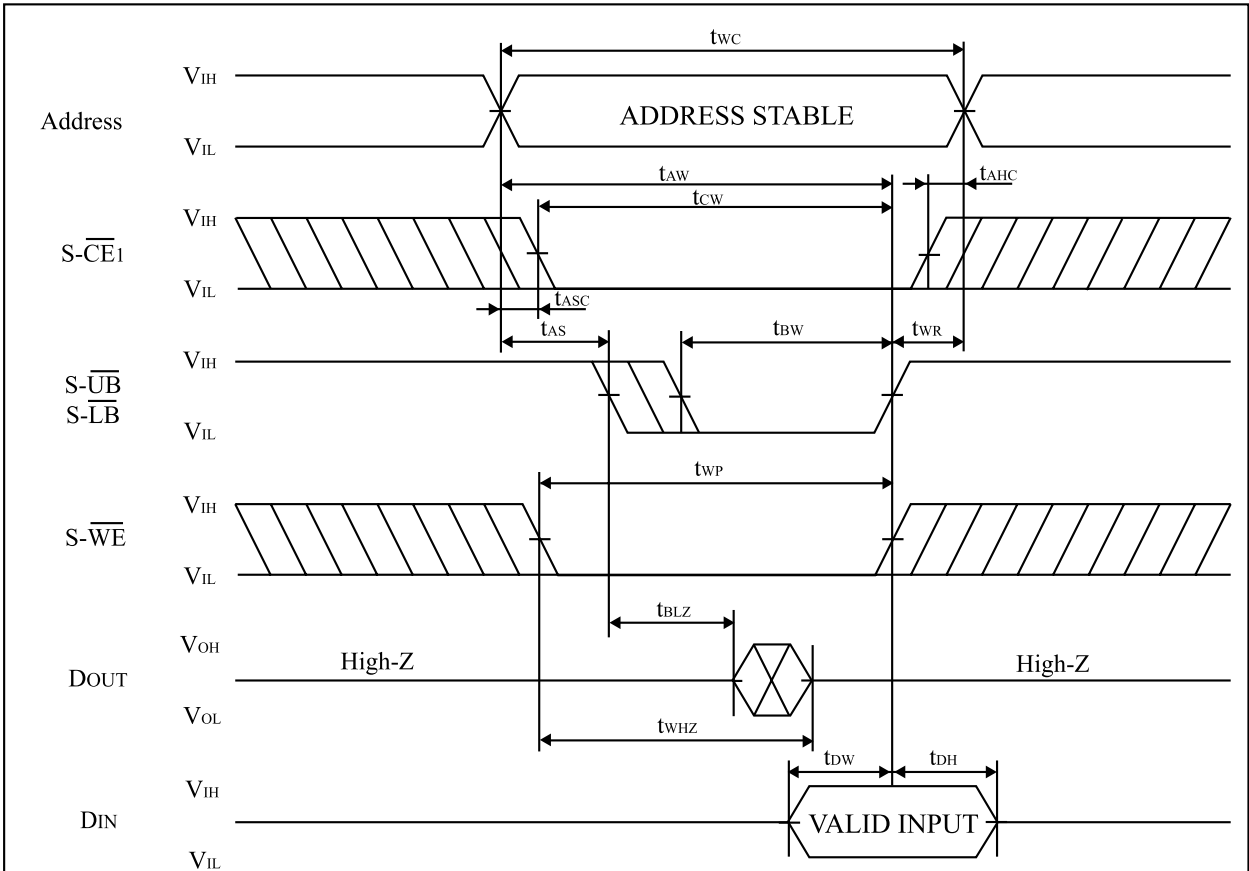
1. Either t_{BAH} or t_{CSH} required for data retention.

13.8 Smartcombo RAM AC Characteristics Timing Chart

Read Cycle Timing Chart

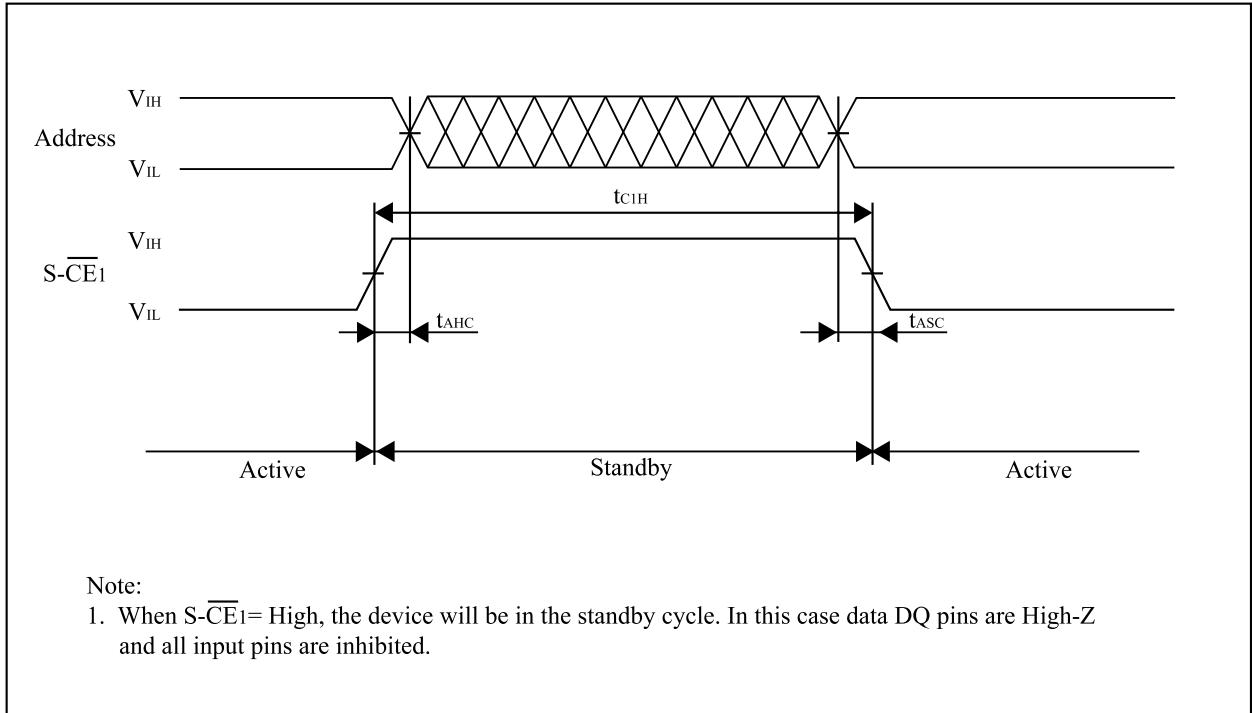


Write Cycle Timing Chart (S- \overline{UB} , S- \overline{LB} Controlled)

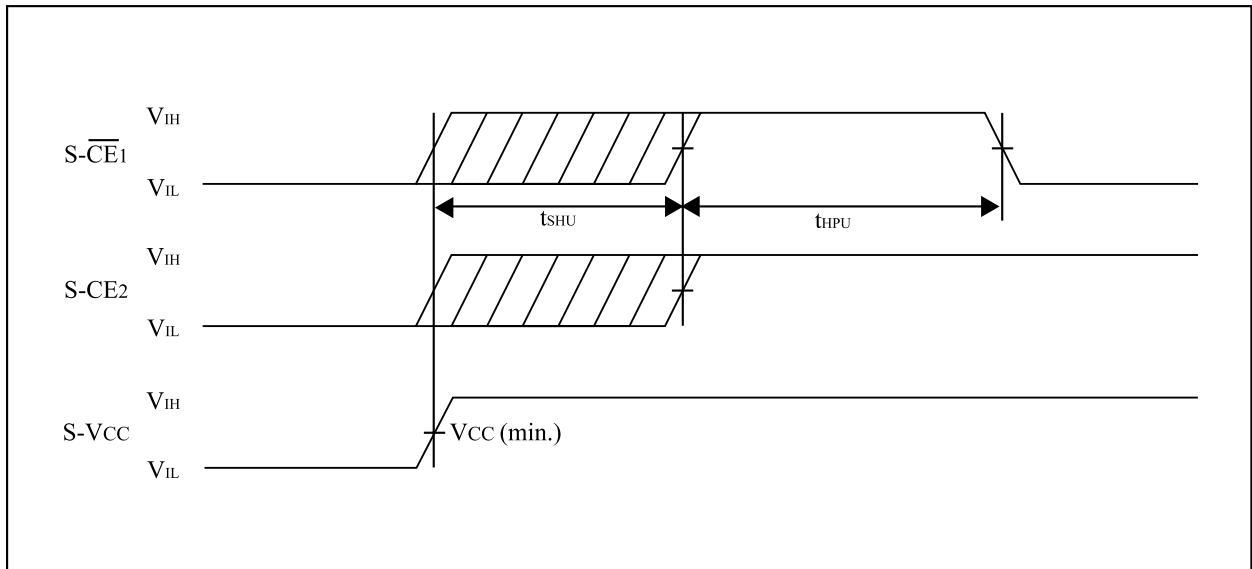


- Notes:
1. If S- \overline{OE} = High, DOUT will be a High-Z state.
 2. S- $\overline{CE2}$ and S- \overline{WE} must be High level for entire write cycle.

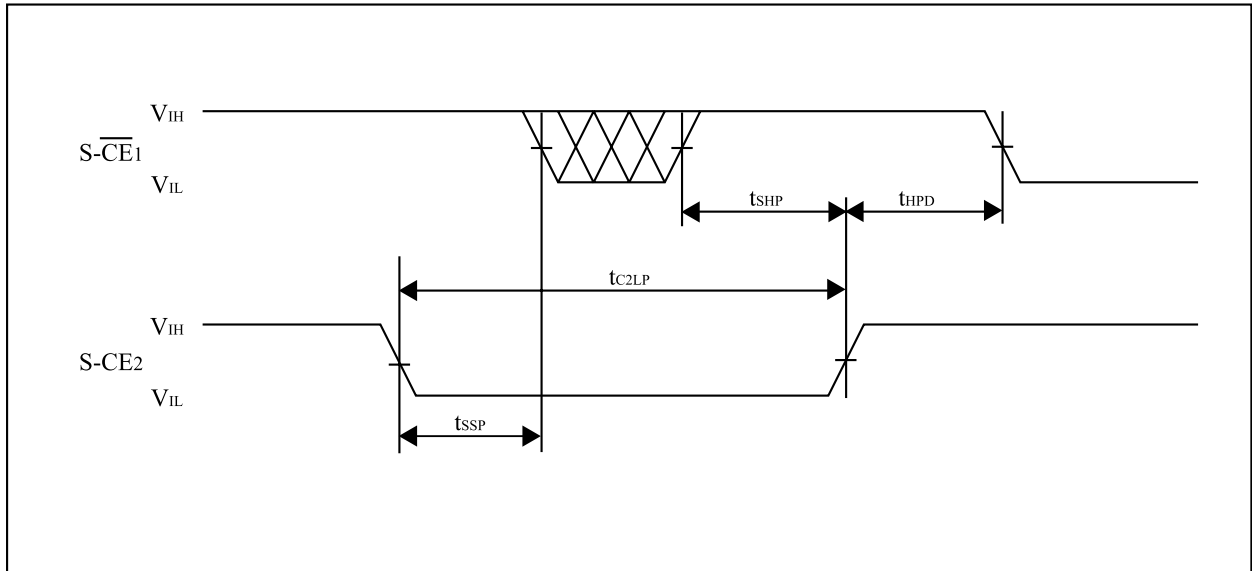
Standby Mode Timing



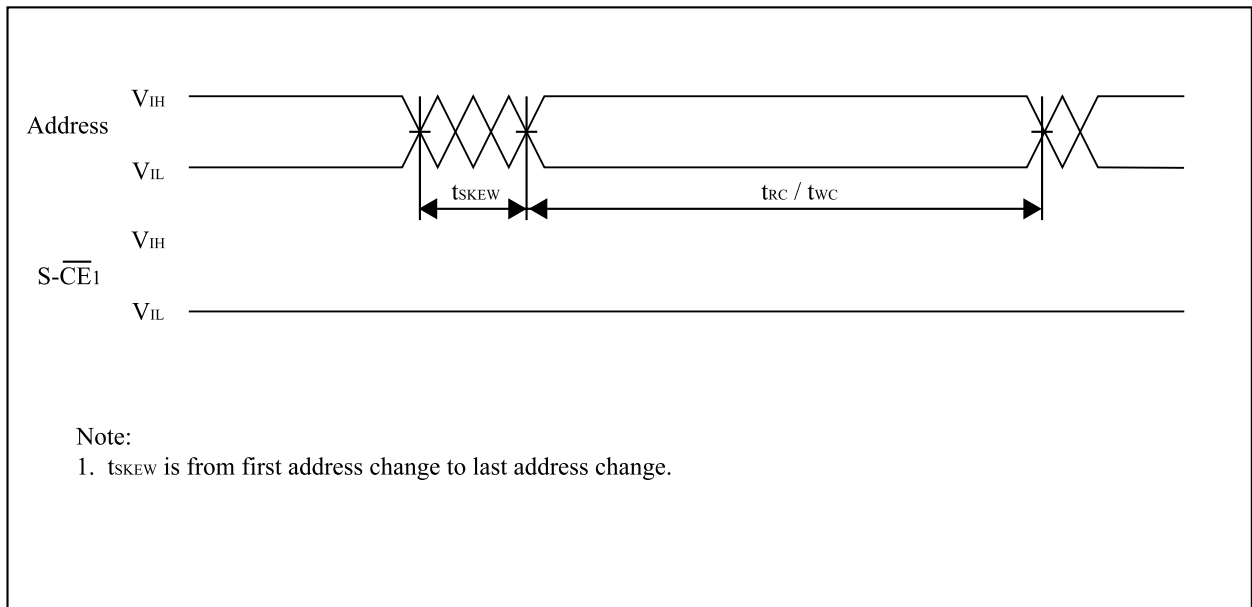
Power Up Timing



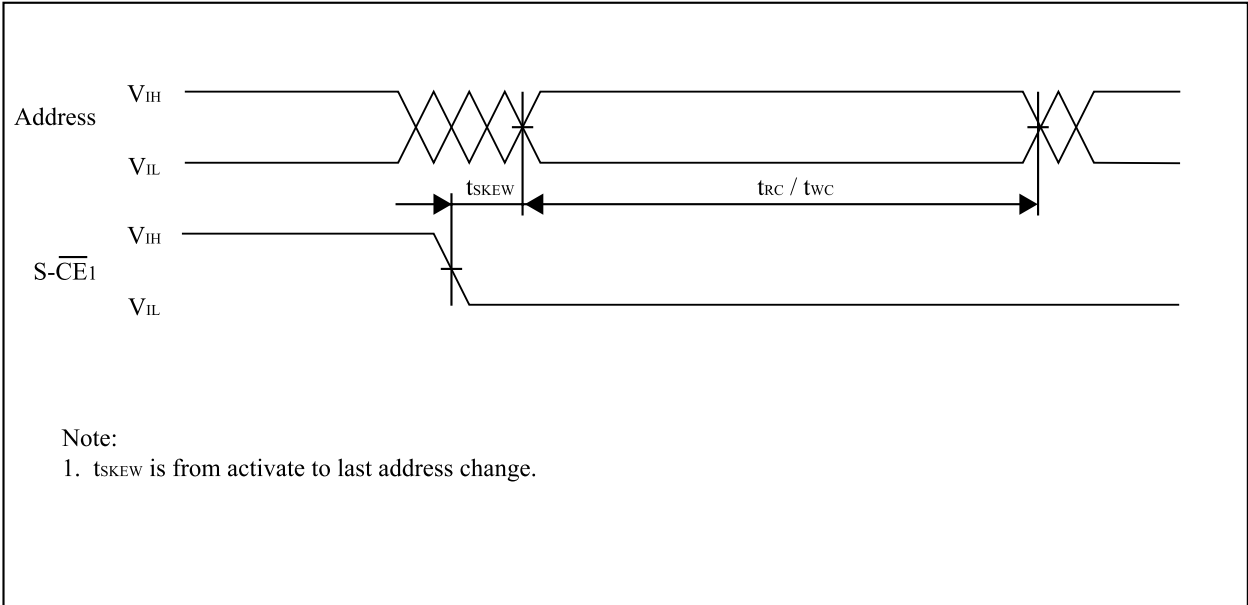
Sleep Mode Timing



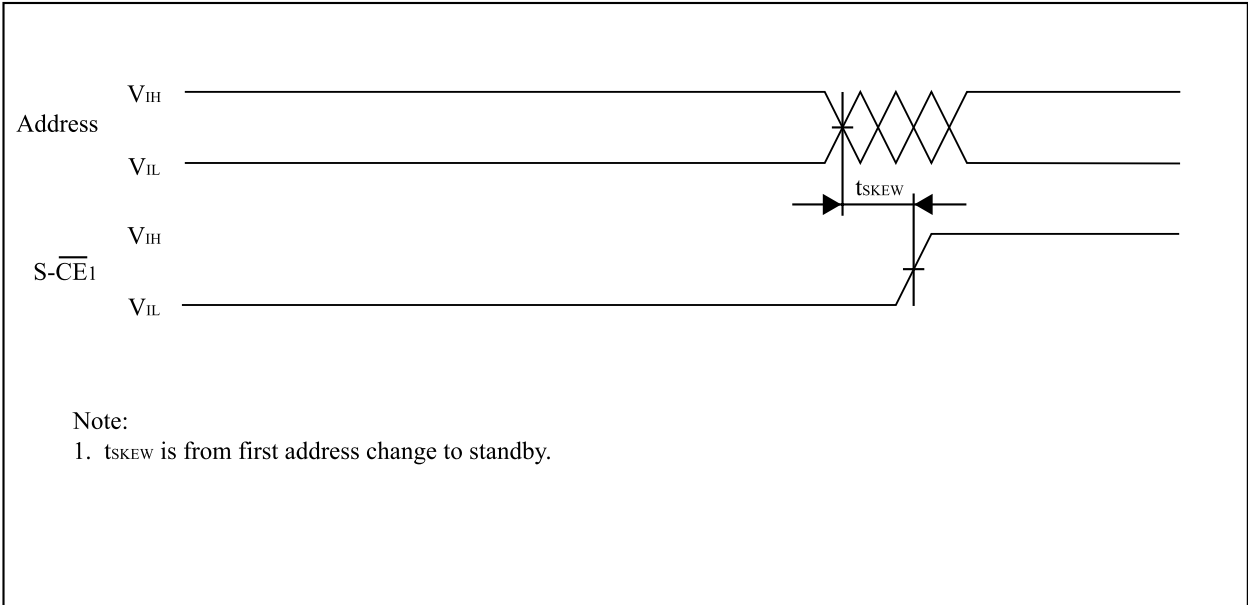
Address Skew Timing 1



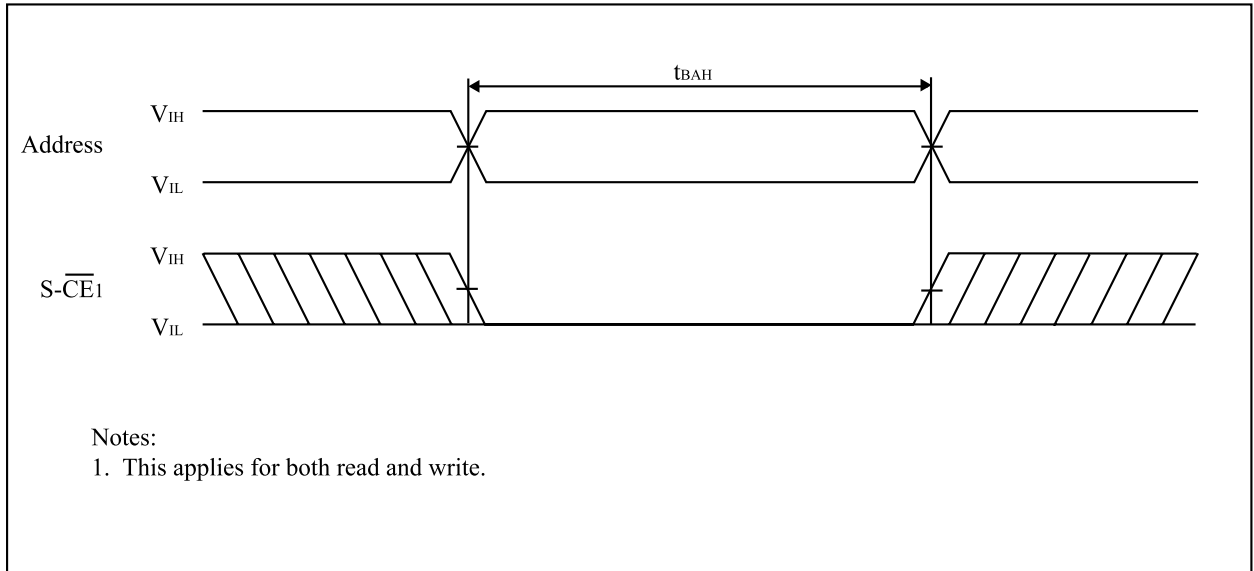
Address Skew Timing 2



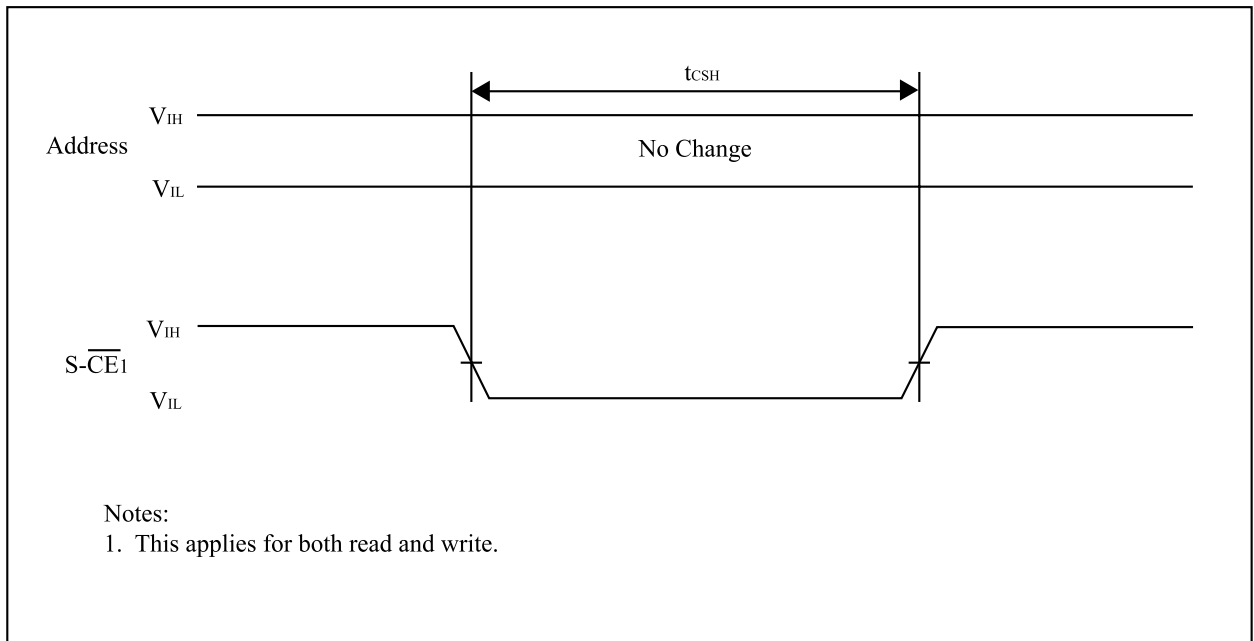
Address Skew Timing 3



Data Retention Timing 1



Data Retention Timing 2



14. Notes

This product is a stacked CSP package that a 64M (x16) bit Flash Memory and a 16M (x16) bit Smartcombo RAM are assembled into.

- Supply Power

Maximum difference (between $F-V_{CC}$ and $S-V_{CC}$) of the voltage is less than 0.3V.

- Power Supply and Chip Enable of Flash Memory and Smartcombo RAM ($F-\overline{CE}$, $S-\overline{CE}_1$, $S-CE_2$)

$S-\overline{CE}_1$ should not be low and $S-CE_2$ should not be high when $F-\overline{CE}$ is low simultaneously.

If the two memories are active together, possibly they may not operate normally by interference noises or data collision on DQ bus.

Both $F-V_{CC}$ and $S-V_{CC}$ are needed to be applied by the recommended supply voltage at the same time expect Smartcombo RAM data retention mode.

- Power Up Sequence

When turning on Flash memory power supply, keep $F-\overline{RST}$ low. After $F-V_{CC}$ reaches over 2.7V, keep $F-\overline{RST}$ low for more than 100 nsec.

- Device Decoupling

The power supply is needed to be designed carefully because one of the Smartcombo RAM and the Flash Memory is in standby mode when the other is active. A careful decoupling of power supplies is necessary between Smartcombo RAM and Flash Memory. Note peak current caused by transition of control signals ($F-\overline{CE}$, $S-\overline{CE}_1$, $S-CE_2$).

15. Flash Memory Data Protection

Noises having a level exceeding the limit specified in the specification may be generated under specific operating conditions on some systems. Such noises, when induced onto $F\text{-}\overline{WE}$ signal or power supply, may be interpreted as false commands and causes undesired memory updating. To protect the data stored in the flash memory against unwanted writing, systems operating with the flash memory should have the following write protect designs, as appropriate:

■ The below describes data protection method.

1. Protection of data in each block

- Any locked block by setting its block lock bit is protected against the data alternation. When $F\text{-}\overline{WP}$ is low, any locked-down block by setting its block lock-down bit is protected from lock status changes. By using this function, areas can be defined, for example, program area (locked blocks), and data area (unlocked blocks).
- For detailed block locking scheme, see Chapter 5.Command Definitions for Flash Memory.

2. Protection of data with $F\text{-}V_{PP}$ control

- When the level of $F\text{-}V_{PP}$ is lower than V_{PPLK} ($F\text{-}V_{PP}$ lockout voltage), write functions to all blocks are disabled. All blocks are locked and the data in the blocks are completely protected.

3. Protection of data with $F\text{-}\overline{RST}$

- Especially during power transitions such as power-up and power-down, the flash memory enters reset mode by bringing $F\text{-}\overline{RST}$ to low, which inhibits write operation to all blocks.
- For detailed description on $F\text{-}\overline{RST}$ control, see Chapter 12.6 AC Electrical Characteristics for Flash Memory, Reset Operations.

■ Protection against noises on $F\text{-}\overline{WE}$ signal

To prevent the recognition of false commands as write commands, system designer should consider the method for reducing noises on $F\text{-}\overline{WE}$ signal.

16. Design Considerations

1. Power Supply Decoupling

To avoid a bad effect to the system by flash memory and Smartcombo RAM power switching characteristics, each device should have a 0.1 μ F ceramic capacitor connected between F-V_{CC} and GND, between F-V_{PP} and GND and between S-V_{CC} and GND.

Low inductance capacitors should be placed as close as possible to package leads.

2. F-V_{PP} Trace on Printed Circuit Boards

Updating the memory contents of flash memories that reside in the target system requires that the printed circuit board designer pay attention to the F-V_{PP} Power Supply trace. Use similar trace widths and layout considerations given to the F-V_{CC} power bus.

3. The Inhibition of Overwrite Operation

Please do not execute reprogramming “0” for the bit which has already been programmed “0”. Overwrite operation may generate unerasable bit.

In case of reprogramming “0” to the data which has been programmed “1”.

- Program “0” for the bit in which you want to change data from “1” to “0”.
- Program “1” for the bit which has already been programmed “0”.

For example, changing data from “1011110110111101” to “1010110110111100” requires “111011111111110” programming.

4. Power Supply

Block erase, full chip erase, word write with an invalid F-V_{PP} (See Chapter 11. DC Electrical Characteristics) produce spurious results and should not be attempted.

Device operations at invalid F-V_{CC} voltage (See Chapter 11. DC Electrical Characteristics) produce spurious results and should not be attempted.

17. Related Document Information⁽¹⁾

Document No.	Document Name
FUM00701	LH28F320BF, LH28F640BF Series Appendix

Note:

1. International customers should contact their local SHARP or distribution sales offices.

18 Package and packing specification

1.Storage Conditions.

1-1.Storage conditions required before opening the dry packing.

- Normal temperature : 5~40°C
- Normal humidity : 80% R.H. max.

1-2.Storage conditions required after opening the dry packing.

In order to prevent moisture absorption after opening, ensure the following storage conditions apply:

(1) Storage conditions for one-time soldering. (Convection reflow*1, IR/Convection reflow.*1)

- Temperature : 5~25°C
- Humidity : 60% R.H. max.
- Period : 96 hours max. after opening.

(2) Storage conditions for two-time soldering. (Convection reflow*1, IR/Convection reflow.*1)

a. Storage conditions following opening and prior to performing the 1st reflow.

- Temperature : 5~25°C。
- Humidity : 60% R.H. max.
- Period : 96 hours max. after opening.

b. Storage conditions following completion of the 1st reflow and prior to performing the 2nd reflow.

- Temperature : 5~25°C。
- Humidity : 60% R.H. max.
- Period : 96 hours max. after completion of the 1st reflow.

*1:Air or nitrogen environment.

1-3.Temporary storage after opening.

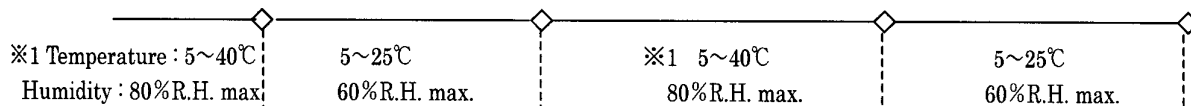
To re-store the devices before soldering, do so only once and use a dry box or place desiccant (with a blue humidity indicator) with the devices and perform dry packing again using heat-sealing.

The storage period, temperature and humidity must be as follows :

(1) Storage temperature and humidity.

※1 : External atmosphere temperature and humidity of the dry packing.

First opening ← X1 → Re-sealing ← Y → Re-opening ← X2 → Mounting



(2) Storage period.

- X1 + X2 : Refer to Section 1-2(1) and (2)a , depending on the mounting method.
- Y : Two weeks max.

2. Baking Condition.

(1) Situations requiring baking before mounting.

- Storage conditions exceed the limits specified in Section 1-2 or 1-3.
- Humidity indicator in the desiccant was already red (pink) when opened.
(Also for re-opening.)

(2) Recommended baking conditions.

- Baking temperature and period :
120+10/-0°C for 1~3 hours.
- The above baking conditions apply since the trays are heat-resistant.

(3) Storage after baking.

- After baking, store the devices in the environment specified in Section 1-2 and mount immediately.

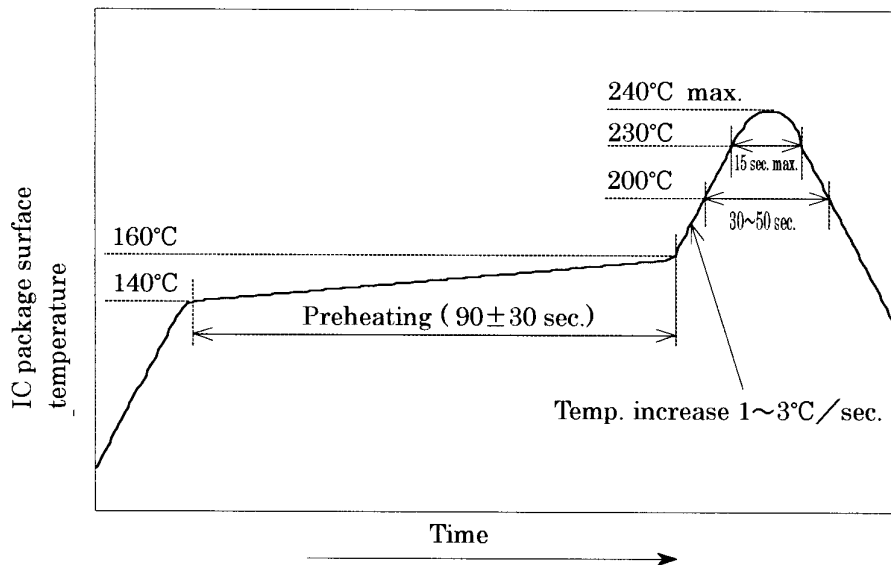
3. Surface mount conditions.

The following soldering condition are recommended to ensure device quality.

3-1. Soldering.

(1) Convection reflow or IR/Convection. (one-time soldering or two-time soldering in air or nitrogen environment)

- Temperature and period :
Peak temperature of 240°C max., above 230°C for 15 sec. max.
Above 200°C for 30~50 sec.
Preheat temperature of 140~160°C for 90 ± 30 sec.
Temperature increase rate of 1~3°C/sec.
- Measuring point : IC package surface.
- Temperature profile :



4. Condition for removal of residual flux.

- (1) Ultrasonic washing power : 25 watts / liter max.
- (2) Washing time : Total 1 minute max.
- (3) Solvent temperature : 15~40°C

5. Package outline specification.

Due to the different manufacturing process, there are tow types of package outline. (see *1)
 No changes are planned on package structure, substrate, and quality or reliability level remains unchanges. Refer to the attached drawing.

6. Markings.

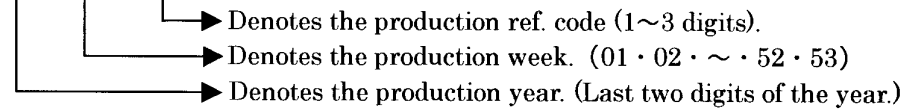
6-1. Marking details. (The information on the package should be given as follows.)

(1) Product name : LRS1805A

(2) Company name : S

(3) Date code

(Example) YY WW XXX



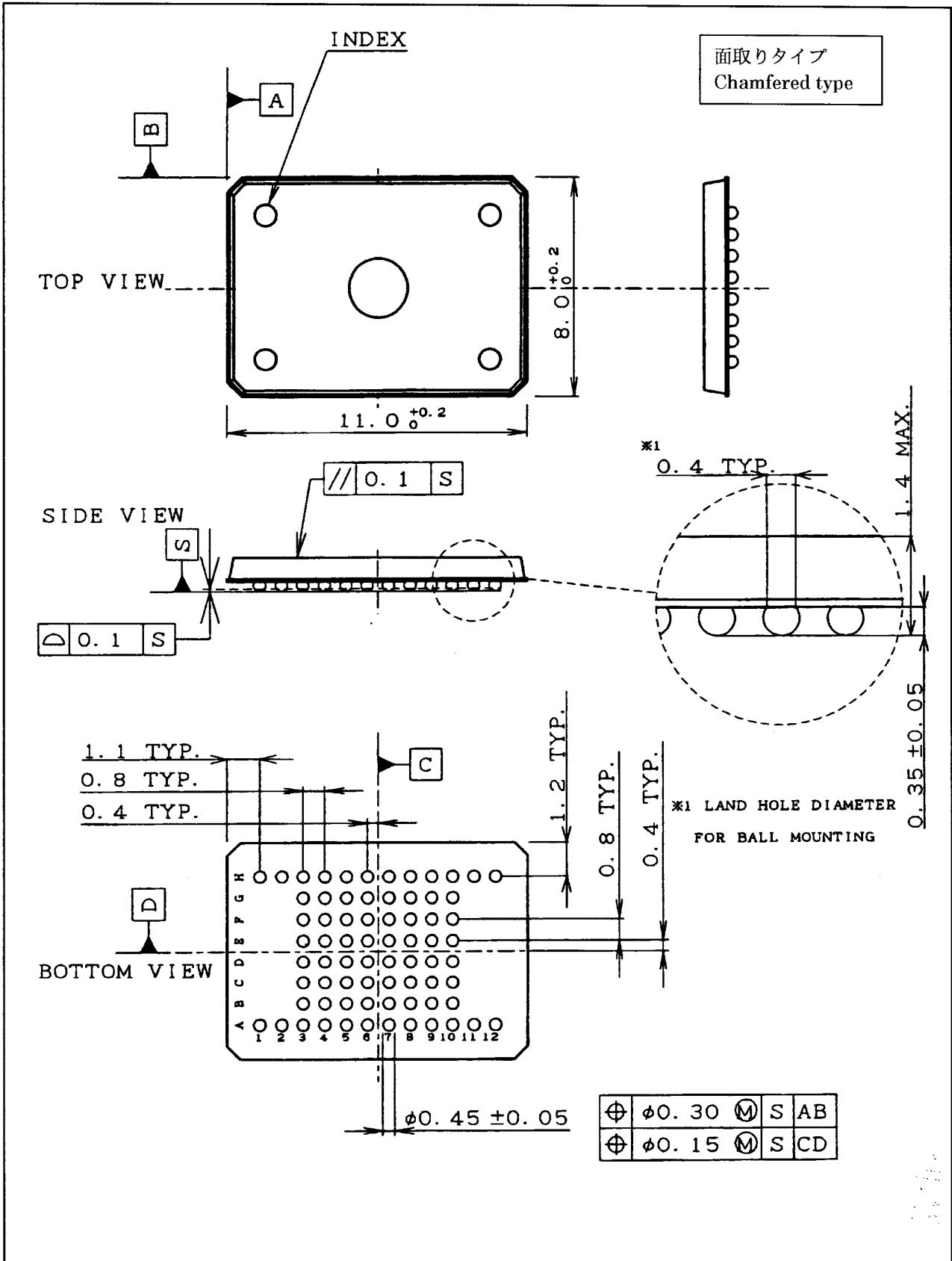
6-2. Marking layout.

The layout is shown in the attached drawing.

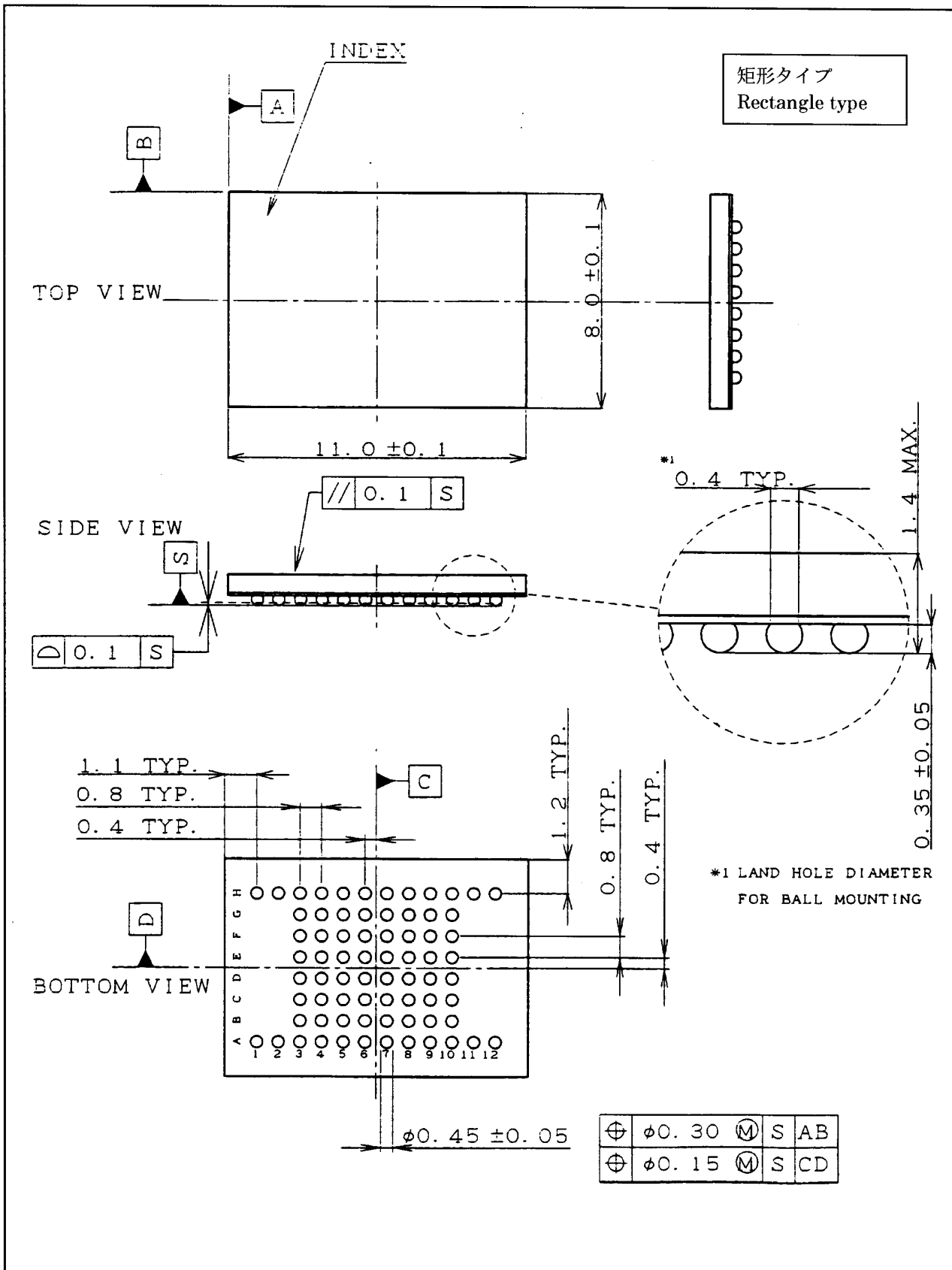
(However, this layout does not specify the size of the marking character and marking position.)

*1 Package outline

Item	Chamfered type	Rectangle type
Manufacturing Process	Devices are encapsulated separately, the cut into individual units by tool.	Multiple devices are encapsulated together, then cut into individual units by saw.
Drawing No.	AA2078	AA2149
Package outline		
Package index mark	Ejector pin mark.	Ink mark.
The word of "BATCH" is printed on the packing label	Not printed	Printed



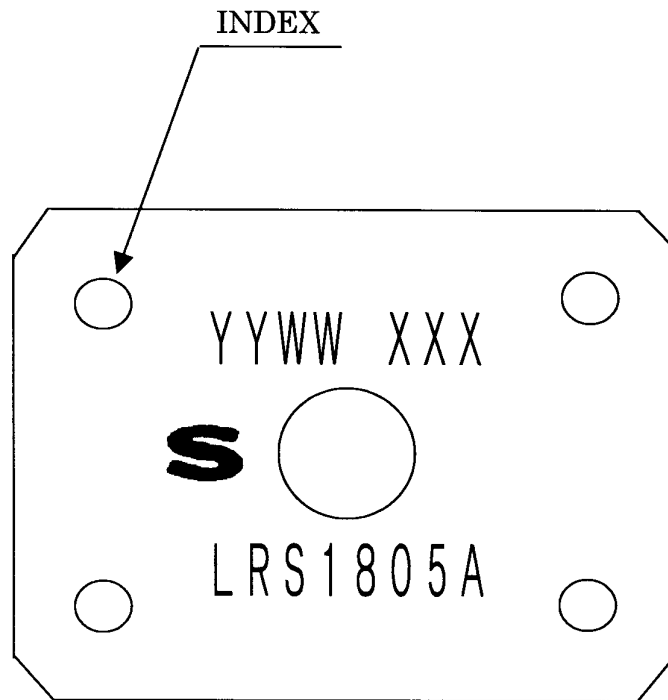
名称 NAME	FBGA072/064-P-0811(LCSP072/064-P-0811)			備考 NOTE
DRAWING NO.	AA2078	単位 UNIT	mm	



名称 NAME	FBGA072/064-P-0811(LCSP072/064-P-0811)			備考 NOTE
DRAWING NO.	AA2149	単位 UNIT	mm	

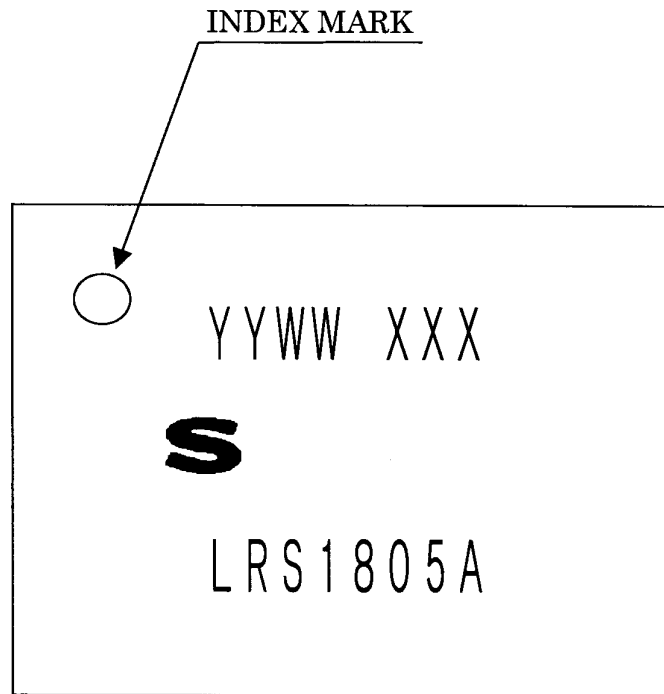
マークレイアウト図
Marking layout

面取りタイプ
Chamfered type



マークレイアウト図
Marking layout

矩形タイプ
Rectangle type



7.Packing Specifications (Dry packing for surface mount packages.)

7-1.Packing materials.

Material name	Material specifications	Purpose
Inner carton	Cardboard (2310 devices / inner carton max.)	Packing the devices. (10 trays / inner carton)
Tray	Conductive plastic (231 devices / tray)	Securing the devices.
Upper cover tray	Conductive plastic (1 tray / inner carton)	Securing the devices.
Laminated aluminum bag	Aluminum polyethylene	Keeping the devices dry.
Desiccant	Silica gel	Keeping the devices dry.
Label	Paper	Indicates part number, quantity, and packed date.
PP band	Polypropylene (3 pcs. / inner carton)	Securing the devices.
Outer carton	Cardboard (9240 devices / outer carton max.)	Outer packing.

(Devices must be placed on the tray in the same direction.)

7-2.Outline dimension of tray.

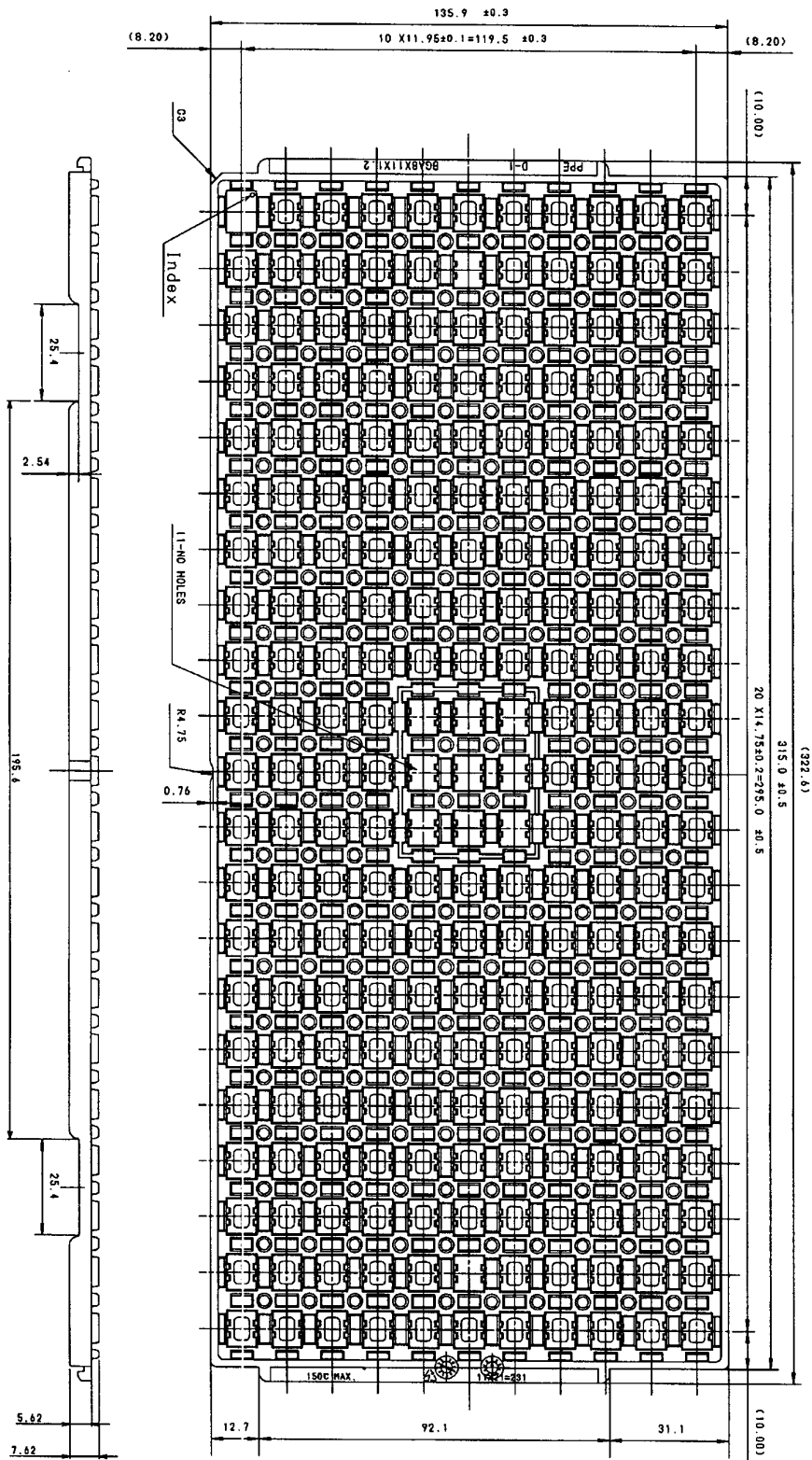
Refer to the attached drawing.

7-3.Outline dimension of carton.

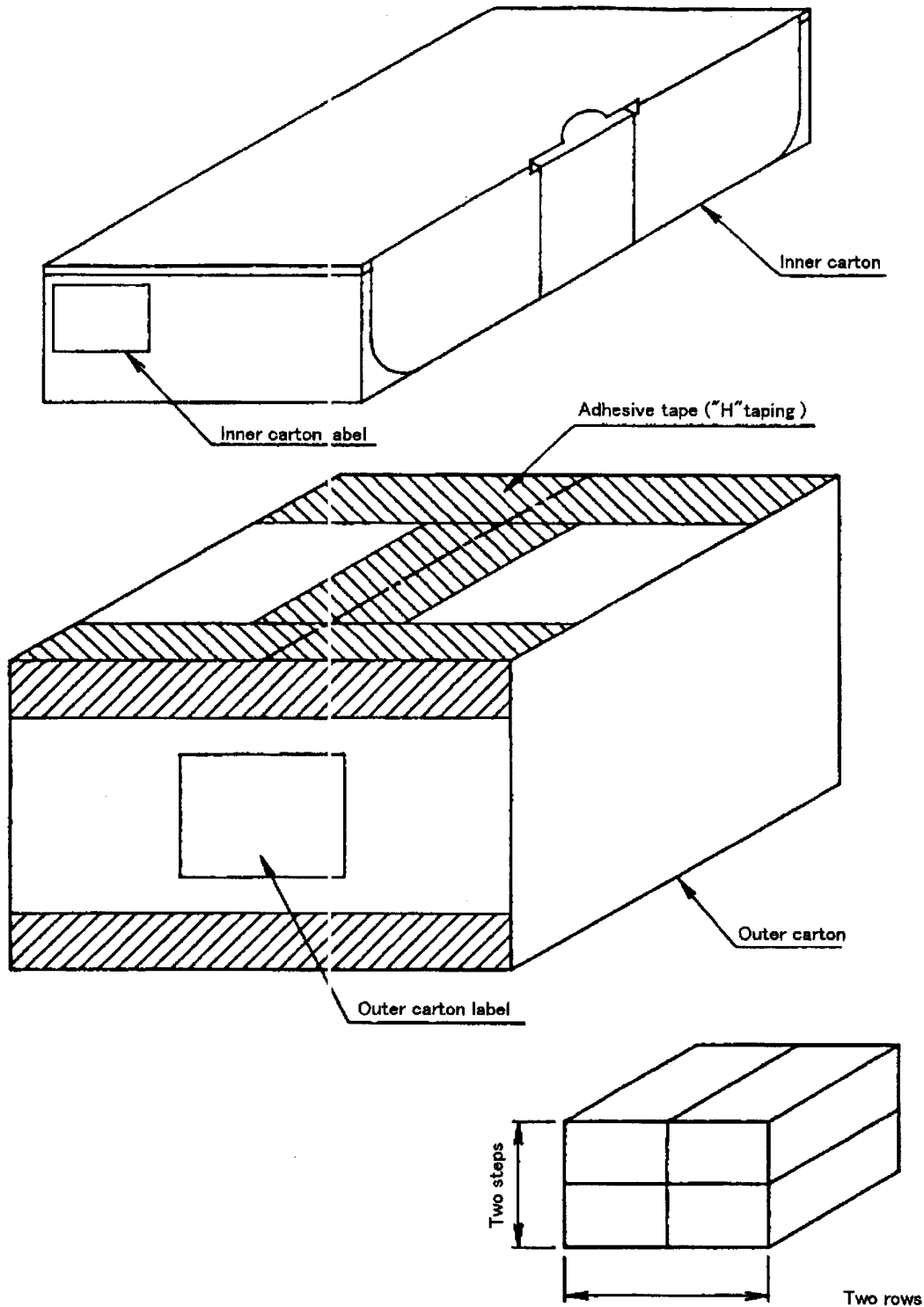
Refer to the attached drawing.

8. Precautions for use.

- (1) Opening must be done on an anti-ESD treated workbench.
All workers must also have undergone anti-ESD treatment.
- (2) The trays have undergone either conductive or anti-ESD treatment.
If another tray is used, make sure it has also undergone conductive or anti-ESD treatment.
- (3) The devices should be mounted the devices within one year of the date of delivery.



名称 NAME	BGA8X11X1.2		備考 NOTE
DRAWING NO.	CV867	単位 UNIT	mm



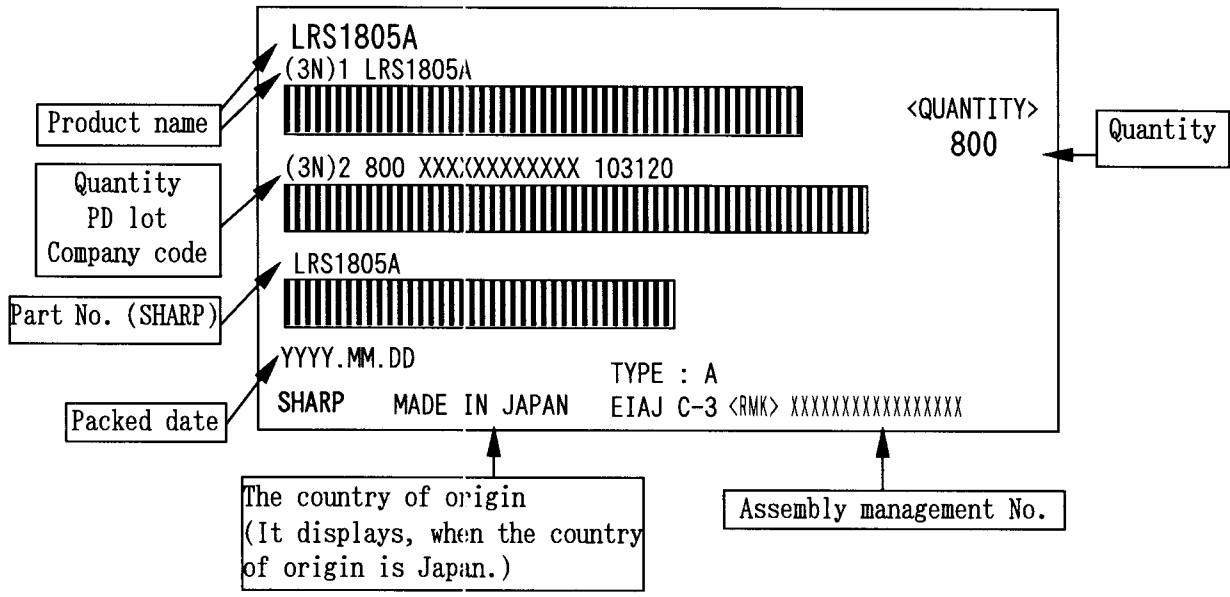
L × W × H

Inner carton - Outer dimensions : 348×152×90

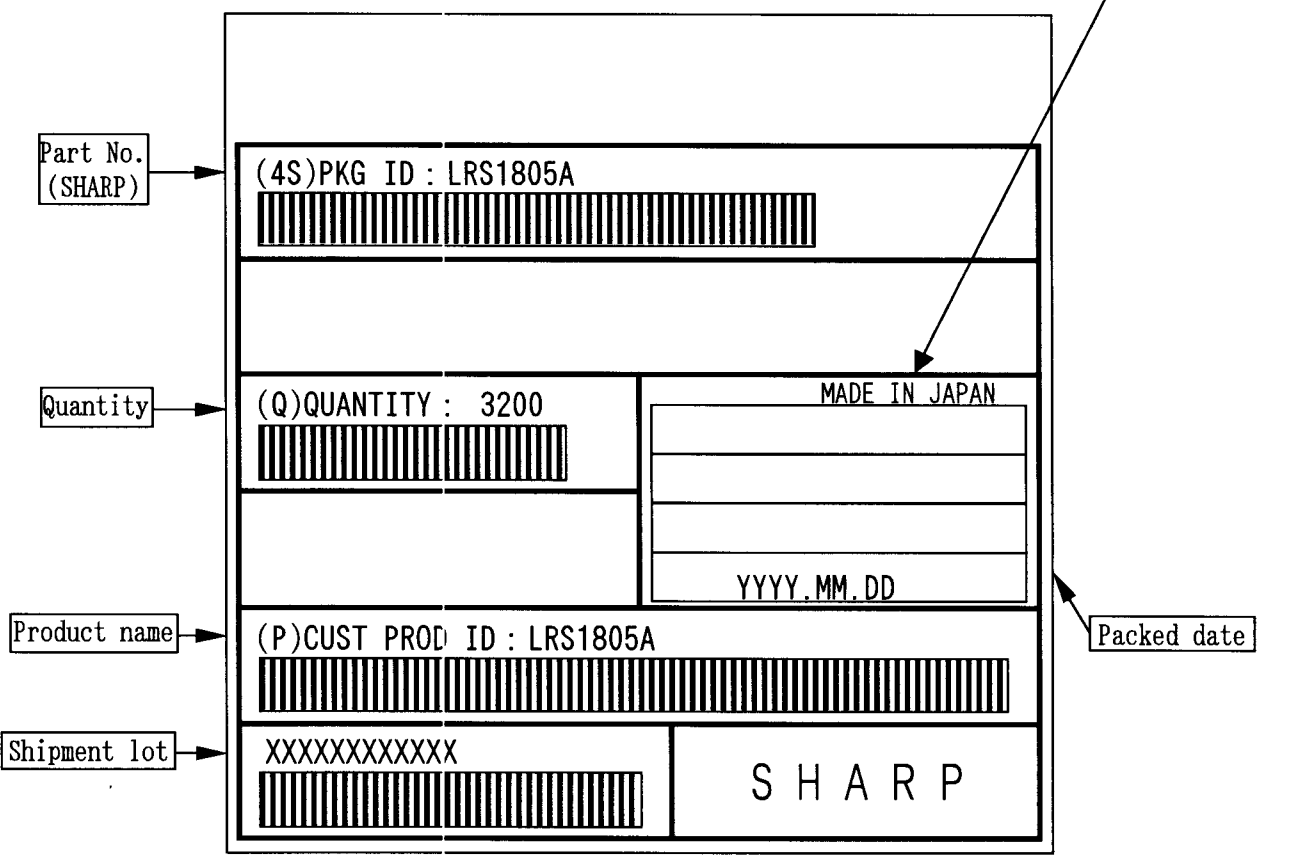
Outer carton - Outer dimensions : 350×335×215

名称 NAME	トレイ品 包装仕様 Packing specifications		備考 NOTE
DRAWING NO.	BJ433	単位 UNIT	
		mm	出荷数量が端数の場合、本仕様と異なることがあります。 There is a possibility different from this specification when the number of shipments is fractions.

Inner carton label



Outer carton label



A-1 RECOMMENDED OPERATING CONDITIONS

A-1.1 At Device Power-Up

AC timing illustrated in Figure A-1 is recommended for the supply voltages and the control signals at device power-up. If the timing in the figure is ignored, the device may not operate correctly.

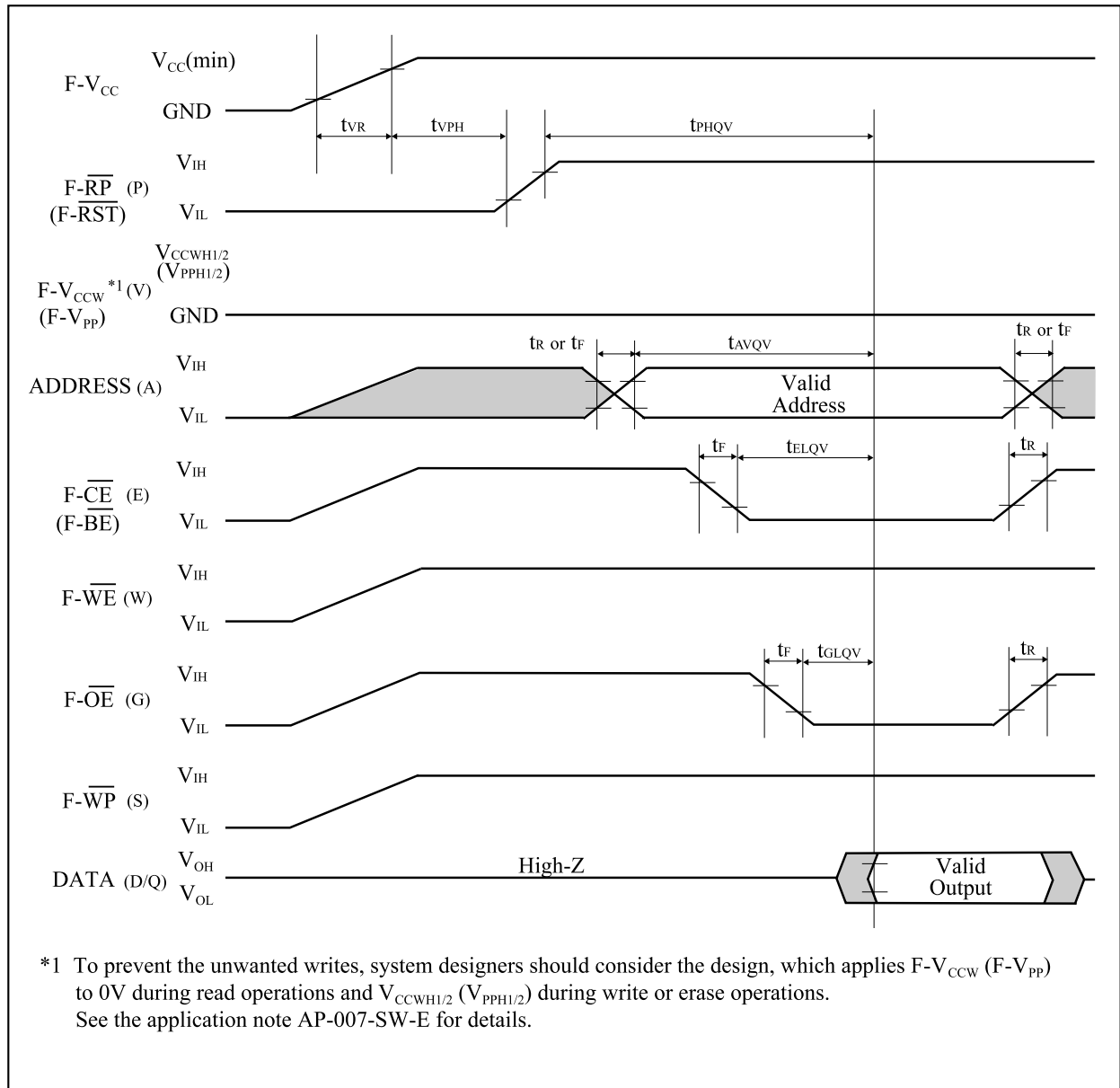


Figure A-1. AC Timing at Device Power-Up

For the AC specifications t_{VR} , t_R , t_F in the figure, refer to the next page. See the “AC Electrical Characteristics for Flash Memory” described in specifications for the supply voltage range, the operating temperature and the AC specifications not shown in the next page.

A-1.1.1 Rise and Fall Time

Symbol	Parameter	Notes	Min.	Max.	Unit
t_{VR}	F- V_{CC} Rise Time	1	0.5	30000	$\mu\text{s}/\text{V}$
t_R	Input Signal Rise Time	1, 2		1	$\mu\text{s}/\text{V}$
t_F	Input Signal Fall Time	1, 2		1	$\mu\text{s}/\text{V}$

NOTES:

1. Sampled, not 100% tested.
2. This specification is applied for not only the device power-up but also the normal operations.

A-1.2 Glitch Noises

Do not input the glitch noises which are below V_{IH} (Min.) or above V_{IL} (Max.) on address, data, reset, and control signals, as shown in Figure A-2 (b). The acceptable glitch noises are illustrated in Figure A-2 (a).

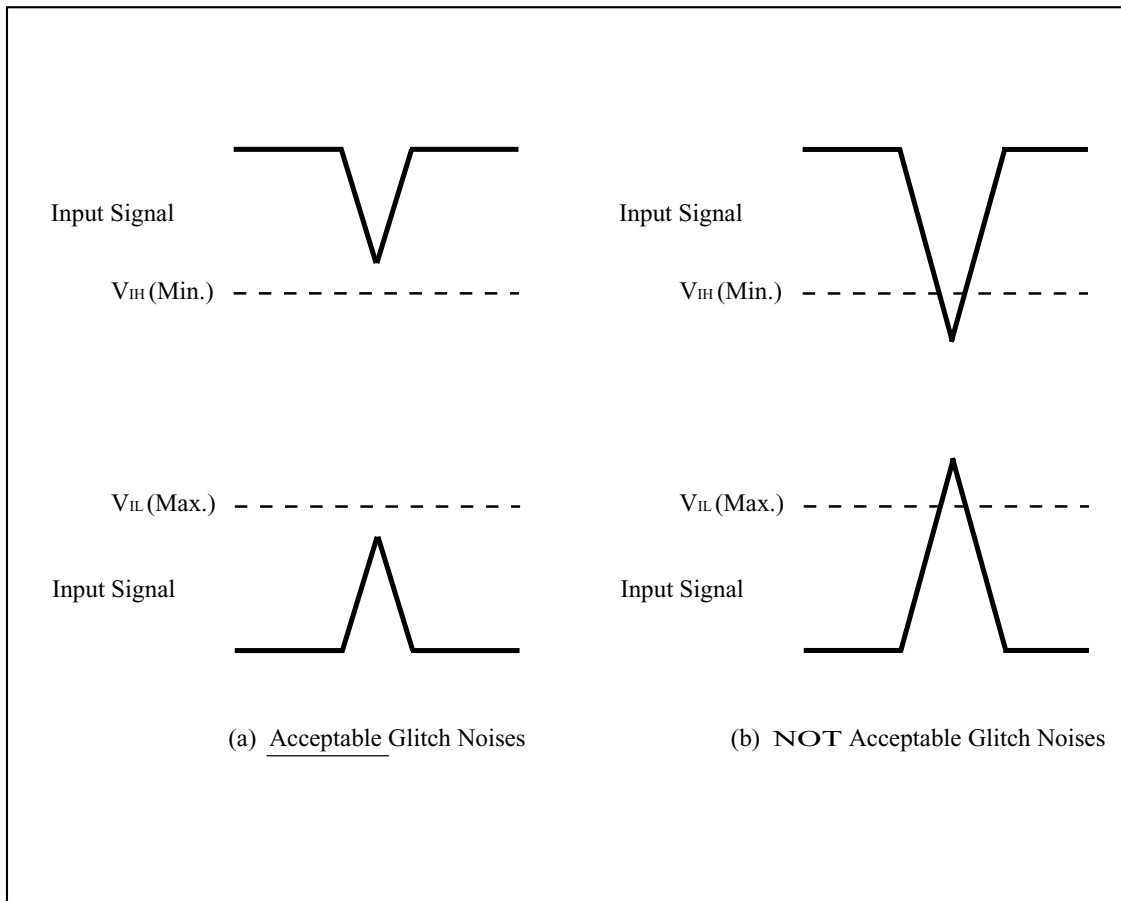


Figure A-2. Waveform for Glitch Noises

See the “DC Electrical Characteristics” described in specifications for V_{IH} (Min.) and V_{IL} (Max.).

A-2 RELATED DOCUMENT INFORMATION⁽¹⁾

Document No.	Document Name
AP-001-SD-E	Flash Memory Family Software Drivers
AP-006-PT-E	Data Protection Method of SHARP Flash Memory
AP-007-SW-E	RP#, V_{pp} Electric Potential Switching Circuit

NOTE:

1. International customers should contact their local SHARP or distribution sales office.

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